FLASH MEMORY

CMOS

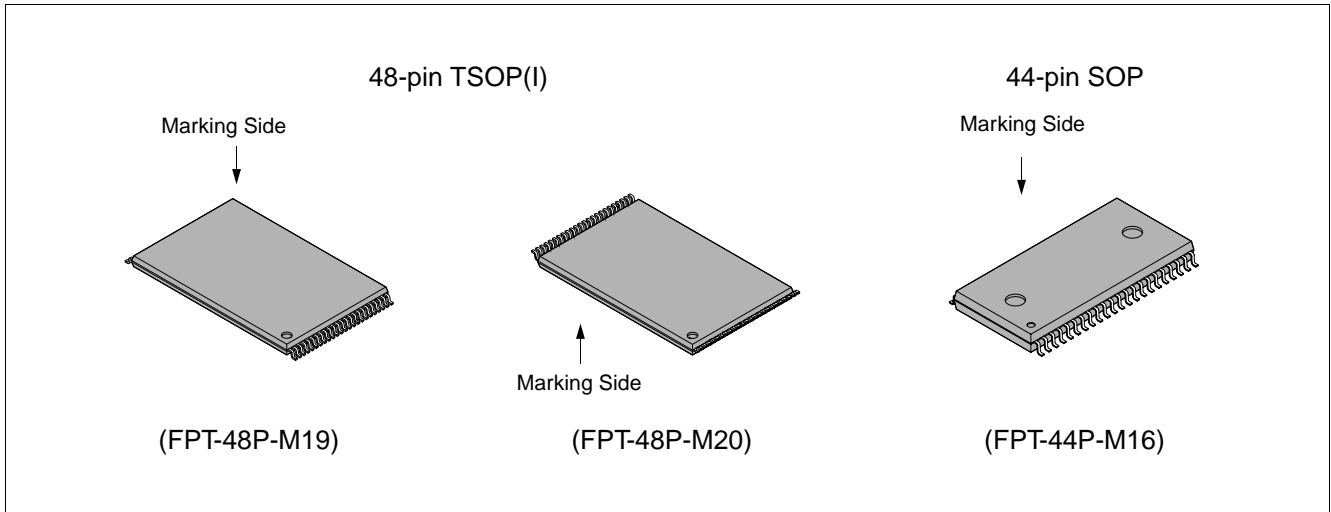# 8M (1M × 8/512K × 16) BIT

MBM29F800TA-55/-70/-90/MBM29F800BA-55/-70/-90

■ FEATURES

- **Single 5.0 V read, write, and erase**
  Minimizes system level power requirements
- **Compatible with JEDEC-standard commands**
  Uses same software commands as E^{2}PROMs
- **Compatible with JEDEC-standard world-wide pinouts**
  48-pin TSOP(I) (Package suffix: PFTN – Normal Bend Type, PFTR – Reversed Bend Type)
  44-pin SOP (Package suffix: PF)
- **Minimum 100,000 write/erase cycles**
- **High performance**
  55 ns maximum access time
- **Sector erase architecture**
  One 16K byte, two 8K bytes, one 32K byte, and fifteen 64K bytes.
  Any combination of sectors can be concurrently erased. Also supports full chip erase.
- **Boot Code Sector Architecture**
  T = Top sector
  B = Bottom sector
- **Embedded Erase™ Algorithms**
  Automatically pre-programs and erases the chip or any sector
- **Embedded Program™ Algorithms**
  Automatically writes and verifies data at specified address
- **Data Polling and Toggle Bit feature for detection of program or erase cycle completion**
- **Ready/Busy output (RY/BY)**
  Hardware method for detection of program or erase cycle completion
- **Low Vcc write inhibit ≤ 3.2 V**
- **Erase Suspend/Resume**
  Suspends the erase operation to allow a read data in another sector within the same device
- **Hardware RESET pin**
  Resets internal state machine to the read mode
- **Sector protection**
  Hardware method disables any combination of sectors from write or erase operations
- **Temporary sector unprotection**
  Temporary sector unprotection via the RESET pin.

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■ PACKAGE

48-pin TSOP(I)

44-pin SOP

Marking Side

Marking Side

Marking Side

(FPT-48P-M19)

(FPT-48P-M20)

(FPT-44P-M16)

■ **GENERAL DESCRIPTION**

The MBM29F800TA/BA is a 8M-bit, 5.0 V-only Flash memory organized as 1M bytes of 8 bits each or 512K words of 16 bits each. The MBM29F800TA/BA is offered in a 48-pin TSOP(I) and 44-pin SOP packages. This device is designed to be programmed in-system with the standard system 5.0 V V_{CC} supply. 12.0 V V_{PP} is not required for write or erase operations. The devices can also be reprogrammed in standard EPROM programmers. The standard MBM29LV800TA/BA offers access times 55 ns and 90 ns, allowing operation of high-speed microprocessors without wait states. To eliminate bus contention the device has separate chip enable ($\overline{CE}$), write enable ($\overline{WE}$), and output enable ($\overline{OE}$) controls.

The MBM29F800TA/BA is pin and command set compatible with JEDEC standard E²PROMs. Commands are written to the command register using standard microprocessor write timings. Register contents serve as input to an internal state-machine which controls the erase and programming circuitry. Write cycles also internally latch addresses and data needed for the programming and erase operations. Reading data out of the devices is similar to reading from12.0 V Flash or EPROM devices.

The MBM29F800TA/BA is programmed by executing the program command sequence. This will invoke the Embedded Program Algorithm which is an internal algorithm that automatically times the program pulse widths and verifies proper cell margin. Typically, each sector can be programmed and verified in less than 0.5 seconds. Erase is accomplished by executing the erase command sequence. This will invoke the Embedded Erase Algorithm which is an internal algorithm that automatically preprograms the array if it is not already programmed before executing the erase operation. During erase, the device automatically times the erase pulse widths and verifies proper cell margin.

Any individual sector is typically erased and verified in 1.0 second (if already completely preprogrammed.).

The devices also features a sector erase architecture. The sector mode allows each sector to be erased and reprogrammed without affecting other sectors. The MBM29F800TA/BA is erased when shipped from the factory.

The devices features single 5.0 V power supply operation for both read and write functions. Internally generated and regulated voltages are provided for the program and erase operations. A low V_{CC} detector automatically inhibits write operations on the loss of power. The end of program or erase is detected by $\overline{Data}$ Polling of DQ_7, by the Toggle Bit feature on DQ_6, or the RY/$\overline{BY}$ output pin. Once the end of a program or erase cycle has been completed, the device internally resets to the read mode.

Fujitsu's Flash technology combines years of EPROM and E²PROM experience to produce the highest levels of quality, reliability, and cost effectiveness. The MBM29F800TA/BA memory electrically erase the entire chip or all bits within a sector simultaneously via Fowler-Nordhiem tunneling. The bytes/words are programmed one byte/word at a time using the EPROM programming mechanism of hot electron injection.

■ FLEXIBLE SECTOR-ERASE ARCHITECTURE

- One 16K byte, two 8K bytes, one 32K byte, and fifteen 64K bytes.
- Individual-sector, multiple-sector, or bulk-erase capability.
- Individual or multiple-sector protection is user definable.

MBM29F800TA	(×8)	(×16)
16K byte	FFFFFH	7FFFFH
8K byte	FBFFFH	7DFFFH
8K byte	F9FFFH	7CFFFH
32K byte	F7FFFH	7BFFFH
64K byte	EFFFFH	77FFFH
64K byte	DFFFFH	6FFFFH
64K byte	CFFFFH	67FFFH
64K byte	BFFFFH	5FFFFH
64K byte	AFFFFH	57FFFH
64K byte	9FFFFH	4FFFFH
64K byte	8FFFFH	47FFFH
64K byte	7FFFFH	3FFFFH
64K byte	6FFFFH	37FFFH
64K byte	5FFFFH	2FFFFH
64K byte	4FFFFH	27FFFH
64K byte	3FFFFH	1FFFFH
64K byte	2FFFFH	17FFFH
64K byte	1FFFFH	0FFFFH
64K byte	0FFFFH	07FFFH
	00000H	00000H

MBM29F800TA Sector Architecture

MBM29F800BA	(×8)	(×16)
64K byte	FFFFFH	7FFFFH
64K byte	EFFFFH	77FFFH
64K byte	DFFFFH	6FFFFH
64K byte	CFFFFH	67FFFH
64K byte	BFFFFH	5FFFFH
64K byte	AFFFFH	57FFFH
64K byte	9FFFFH	4FFFFH
64K byte	8FFFFH	47FFFH
64K byte	7FFFFH	3FFFFH
64K byte	6FFFFH	37FFFH
64K byte	5FFFFH	2FFFFH
64K byte	4FFFFH	27FFFH
64K byte	3FFFFH	1FFFFH
64K byte	2FFFFH	17FFFH
64K byte	1FFFFH	0FFFFH
32K byte	0FFFFH	07FFFH
8K byte	07FFFH	03FFFH
8K byte	05FFFH	02FFFH
16K byte	03FFFH	01FFFH
	00000H	00000H

MBM29F800BA Sector Architecture

■ PRODUCT LINE UP

Part No.		MBM29F800TA/MBM29F800BA		
Ordering Part No.	V_{CC} = 5.0 V ± 5 %	-55	—	—
	V_{CC} = 5.0 V ± 10 %	—	-70	-90
Max. Address Access Time (ns)		55	70	90
Max. $\overline{CE}$ Access Time (ns)		55	70	90
Max. $\overline{OE}$ Access Time (ns)		30	30	40

■ BLOCK DIAGRAM

■ CONNECTION DIAGRAMS

TSOP(I)

(Marking Side)

MBM29F800TA/MBM29F800BA
Standard Pinout

Left	Pin		Pin	Right
A15	1		48	A16
A14	2		47	BYTE
A13	3		46	Vss
A12	4		45	DQ15/A-1
A11	5		44	DQ7
A10	6		43	DQ14
A9	7		42	DQ6
A8	8		41	DQ13
N.C.	9		40	DQ5
N.C.	10		39	DQ12
WE	11		38	DQ4
RESET	12		37	Vcc
N.C.	13		36	DQ11
N.C.	14		35	DQ3
RY/BY	15		34	DQ10
A18	16		33	DQ2
A17	17		32	DQ9
A7	18		31	DQ1
A6	19		30	DQ8
A5	20		29	DQ0
A4	21		28	OE
A3	22		27	Vss
A2	23		26	CE
A1	24		25	A0

FPT-48P-M19

(Marking Side)

MBM29F800TA/MBM29F800BA
Reverse Pinout

Left	Pin		Pin	Right
A1	24		25	A0
A2	23		26	CE
A3	22		27	Vss
A4	21		28	OE
A5	20		29	DQ0
A6	19		30	DQ8
A7	18		31	DQ1
A17	17		32	DQ9
A18	16		33	DQ2
RY/BY	15		34	DQ10
N.C.	14		35	DQ3
N.C.	13		36	DQ11
RESET	12		37	Vcc
WE	11		38	DQ4
N.C.	10		39	DQ12
N.C.	9		40	DQ5
A8	8		41	DQ13
A9	7		42	DQ6
A10	6		43	DQ14
A11	5		44	DQ7
A12	4		45	DQ15/A-1
A13	3		46	Vss
A14	2		47	BYTE
A15	1		48	A16

FPT-48P-M20

SOP
(Top View)

Left	Pin		Pin	Right
RY/BY	1		44	RESET
A18	2		43	WE
A17	3		42	A8
A7	4		41	A9
A6	5		40	A10
A5	6		39	A11
A4	7		38	A12
A3	8		37	A13
A2	9		36	A14
A1	10		35	A15
A0	11		34	A16
CE	12		33	BYTE
Vss	13		32	Vss
OE	14		31	DQ15/A-1
DQ0	15		30	DQ7
DQ8	16		29	DQ14
DQ1	17		28	DQ6
DQ9	18		27	DQ13
DQ2	19		26	DQ5
DQ10	20		25	DQ12
DQ3	21		24	DQ4
DQ11	22		23	Vcc

FPT-44P-M16

■ **LOGIC SYMBOL**

Table 1 MBM29F800TA/BA Pin Configuration

Pin	Function
A$_{-1}$, A$_0$ to A$_{18}$	Address Inputs
DQ$_0$ to DQ$_{15}$	Data Inputs/Outputs
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
$\overline{WE}$	Write Enable
RY/$\overline{BY}$	Ready/Busy Output
$\overline{RESET}$	Hardware Reset Pin/ Temporary Sector Unprotection
$\overline{BYTE}$	Selects 8-bit or 16-bit mode
N.C.	No Internal Connection
V$_{SS}$	Device Ground
V$_{CC}$	Device Power Supply

Table 2   MBM29F800TA/BA User Bus Operation ($\overline{\text{BYTE}} = V_{IH}$)

Operation	$\overline{\text{CE}}$	$\overline{\text{OE}}$	$\overline{\text{WE}}$	A_0	A_1	A_6	A_9	DQ_0 to DQ_{15}	$\overline{\text{RESET}}$
Auto-Select Manufacturer Code (1)	L	L	H	L	L	L	V_{ID}	Code	H
Auto-Select Device Code (1)	L	L	H	H	L	L	V_{ID}	Code	H
Read (3)	L	L	H	A_0	A_1	A_6	A_9	D_{OUT}	H
Standby	H	X	X	X	X	X	X	HIGH-Z	H
Output Disable	L	H	H	X	X	X	X	HIGH-Z	H
Write	L	H	L	A_0	A_1	A_6	A_9	D_{IN}	H
Enable Sector Protection (2)	L	V_{ID}	⎍	X	X	L	V_{ID}	X	H
Verify Sector Protection (2)	L	L	H	L	H	L	V_{ID}	Code	H
Temporary Sector Unprotection	X	X	X	X	X	X	X	X	V_{ID}
Reset (Hardware)/Standby	X	X	X	X	X	X	X	HIGH-Z	L

Table 3   MBM29F800TA/BA User Bus Operation ($\overline{\text{BYTE}} = V_{IL}$)

Operation	$\overline{\text{CE}}$	$\overline{\text{OE}}$	$\overline{\text{WE}}$	DQ_{15}/A_{-1}	A_0	A_1	A_6	A_9	DQ_0 to DQ_7	$\overline{\text{RESET}}$
Auto-Select Manufacturer Code (1)	L	L	H	L	L	L	L	V_{ID}	Code	H
Auto-Select Device Code (1)	L	L	H	L	H	L	L	V_{ID}	Code	H
Read (3)	L	L	H	A_{-1}	A_0	A_1	A_6	A_9	D_{OUT}	H
Standby	H	X	X	X	X	X	X	X	HIGH-Z	H
Output Disable	L	H	H	X	X	X	X	X	HIGH-Z	H
Write (Program/Erase)	L	H	L	A_{-1}	A_0	A_1	A_6	A_9	D_{IN}	H
Enable Sector Protection (2)	L	V_{ID}	⎍	X	X	H	L	V_{ID}	X	H
Verify Sector Protection (2)	L	L	H	L	L	H	L	V_{ID}	Code	H
Temporary Sector Unprotection	X	X	X	X	X	X	X	X	X	V_{ID}
Reset (Hardware)/Standby	X	X	X	X	X	X	X	X	HIGH-Z	L

Legend: L = V_{IL}, H = V_{IH}, X = V_{IL} or V_{IH}, ⎍ = Pulse input. See DC Characteristics for voltage levels.

Notes: 1. Manufacturer and device codes may also be accessed via a command register write sequence. See Table 7.
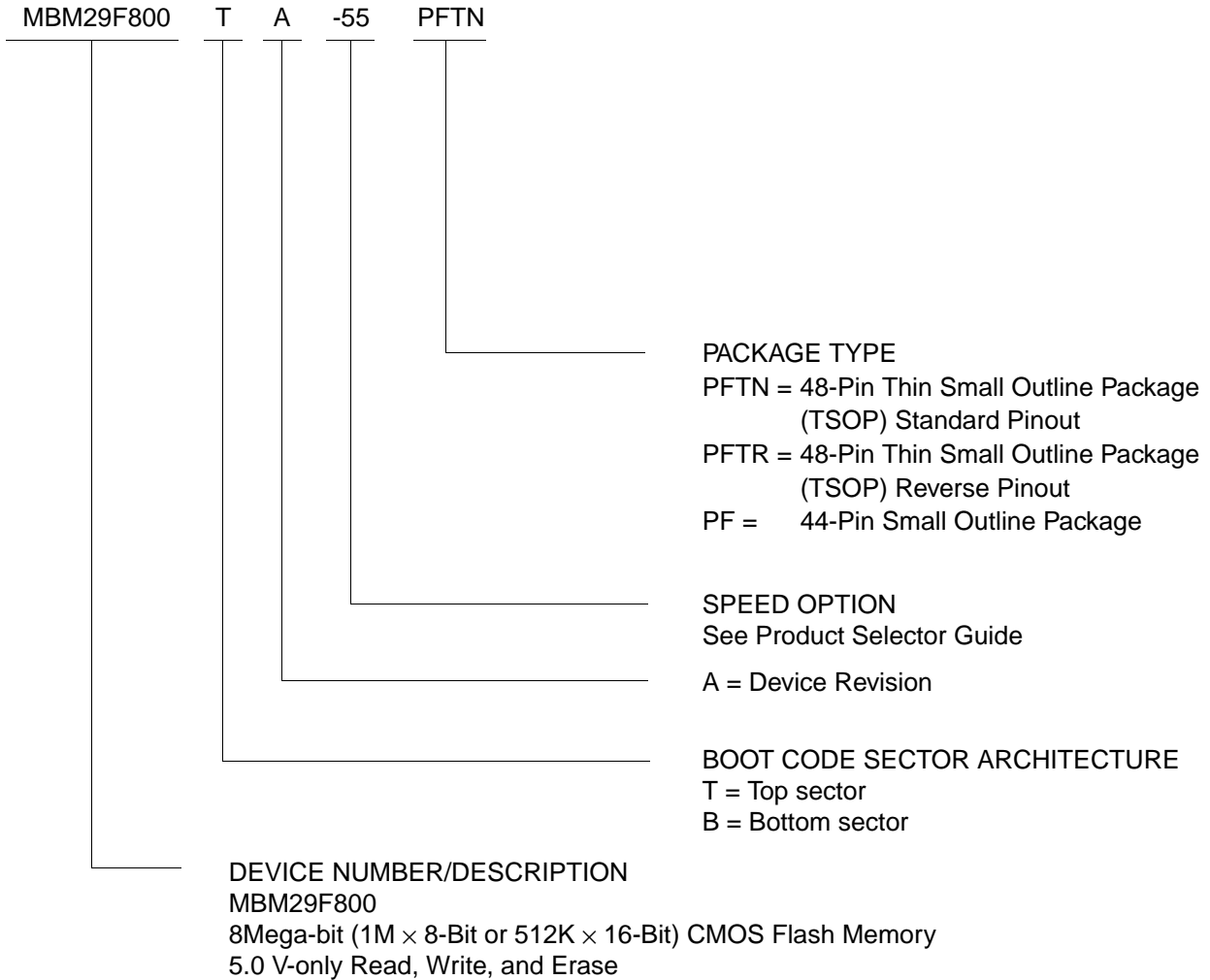2. Refer to the section on Sector Protection.
3. $\overline{\text{WE}}$ can be V_{IL} if $\overline{\text{OE}}$ is V_{IL}, $\overline{\text{OE}}$ at V_{IH} initiates the write operations.

■ ORDERING INFORMATION

Standard Products

Fujitsu standard products are available in several packages. The order number is formed by a combination of:

MBM29F800   T   A   -55   PFTN

PACKAGE TYPE
PFTN = 48-Pin Thin Small Outline Package
         (TSOP) Standard Pinout
PFTR = 48-Pin Thin Small Outline Package
         (TSOP) Reverse Pinout
PF =   44-Pin Small Outline Package

SPEED OPTION
See Product Selector Guide

A = Device Revision

BOOT CODE SECTOR ARCHITECTURE
T = Top sector
B = Bottom sector

DEVICE NUMBER/DESCRIPTION
MBM29F800
8Mega-bit (1M × 8-Bit or 512K × 16-Bit) CMOS Flash Memory
5.0 V-only Read, Write, and Erase

■ **FUNCTIONAL DESCRIPTION**

Read Mode

The MBM29F800TA/BA has two control functions which must be satisfied in order to obtain data at the outputs. $\overline{CE}$ is the power control and should be used for a device selection. $\overline{OE}$ is the output control and should be used to gate data to the output pins if a device is selected.

Address access time (t_{ACC}) is equal to the delay from stable addresses to valid output data. The chip enable access time (t_{CE}) is the delay from stable addresses and stable $\overline{CE}$ to valid data at the output pins. The output enable access time is the delay from the falling edge of $\overline{OE}$ to valid data at the output pins (Assuming the addresses have been stable for at least t_{ACC} - t_{CE} time).

Standby Mode

There are two ways to implement the standby mode on the MBM29F800TA/BA devices, one using both the $\overline{CE}$ and $\overline{RESET}$ pins; the other via the $\overline{RESET}$ pin only.

When using both pins, a CMOS standby mode is achieved with $\overline{CE}$ and $\overline{RESET}$ inputs both held at V_{CC} ± 0.3 V. Under this condition the current consumed is less than 5 μA. A TTL standby mode is achieved with $\overline{CE}$ and $\overline{RESET}$ pins held at V_{IH}. Under this condition the current is reduced to approximately 1mA. During Embedded Algorithm operation, V_{CC} Active current (I_{CC2}) is required even $\overline{CE}$ = V_{IH}. The device can be read with standard access time (t_{CE}) from either of these standby modes.

When using the $\overline{RESET}$ pin only, a CMOS standby mode is achieved with $\overline{RESET}$ input held at V_{SS} ± 0.3 V ($\overline{CE}$ = "H" or "L"). Under this condition the current is consumed is less than 5 μA. A TTL standby mode is achieved with $\overline{RESET}$ pin held at V_{IL}, ($\overline{CE}$= "H" or "L"). Under this condition the current required is reduced to approximately 1mA. Once the $\overline{RESET}$ pin is taken high, the device requires 500 ns of wake up time before outputs are valid for read access.

In the standby mode the outputs are in the high impedance state, independent of the $\overline{OE}$ input.

Output Disable

With the $\overline{OE}$ input at a logic high level (V_{IH}), output from the device is disabled. This will cause the output pins to be in a high impedance state.

Autoselect

The autoselect mode allows the reading out of a binary code from the device and will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the devices to be programmed with its corresponding programming algorithm. This mode is functional over the entire temperature range of the device.

To activate this mode, the programming equipment must force V_{ID} (11.5 V to 12.5 V) on address pin A_9. Two identifier bytes may then be sequenced from the devices outputs by toggling address A_0 from V_{IL} to V_{IH}. All addresses are don't cares except A_0, A_1, A_6, and A_{-1} (See Tables 4.1).

The manufacturer and device codes may also be read via the command register, for instances when the MBM29F800TA/BA is erased or programmed in a system without access to high voltage on the A_9 pin. The command sequence is illustrated in Table 7 (refer to Autoselect Command section).

Byte 0 (A_0 = V_{IL}) represents the manufacturer's code (Fujitsu = 04H) and A_0 = V_{IH} represents the device identifier code (MBM29F800TA = D6H and MBM29F800BA = 58H for ×8 mode; MBM29F800TA = 22D6H and MBM29F800BA = 2258H for ×16 mode). These two bytes/words are given in the tables 4.1 and 4.2. All identifiers for manufacturers and device will exhibit odd parity with DQ_7 defined as the parity bit. In order to read the proper device codes when executing the autoselect, A_1 must be V_{IL} (See Tables 4.1 and 4.2).

Table 4 .1   MBM29F800TA/BA Sector Protection Verify Autoselect Codes

Type			A$_{12}$ to A$_{18}$	A$_6$	A$_1$	A$_0$	A$_{-1}$*1	Code (HEX)
Manufacture's Code			X	V$_{IL}$	V$_{IL}$	V$_{IL}$	V$_{IL}$	04H
Device Code	MBM29F800TA	Byte	X	V$_{IL}$	V$_{IL}$	V$_{IH}$	V$_{IL}$	D6H
		Word					X	22D6H
	MBM29F800BA	Byte	X	V$_{IL}$	V$_{IL}$	V$_{IH}$	V$_{IL}$	58H
		Word					X	2258H
Sector Protection			Sector Addresses	V$_{IL}$	V$_{IH}$	V$_{IL}$	V$_{IL}$	01H*2

*1: A$_{-1}$ is for Byte mode.

*2: Outputs 01H at protected sector addresses and outputs 00H at unprotected sector addresses.

Table 4 .2   Expanded Autoselect Code Table

Type			Code	DQ$_{15}$	DQ$_{14}$	DQ$_{13}$	DQ$_{12}$	DQ$_{11}$	DQ$_{10}$	DQ$_9$	DQ$_8$	DQ$_7$	DQ$_6$	DQ$_5$	DQ$_4$	DQ$_3$	DQ$_2$	DQ$_1$	DQ$_0$
Manufacture's Code			04H	A$_{-1}$/0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0
Device Code	MBM29F800TA	(B)	D6H	A$_{-1}$	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	1	1	0	1	0	1	1	0
		(W)	22D6H	0	0	1	0	0	0	1	0	1	1	0	1	0	1	1	0
	MBM29F800BA	(B)	58H	A$_{-1}$	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	0	1	0	1	1	0	0	0
		(W)	2258H	0	0	1	0	0	0	1	0	0	1	0	1	1	0	0	0
Sector Protection			01H	A$_{-1}$/0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1

(B): Byte mode
(W): Word mode

Write

Device erasure and programming are accomplished via the command register. The contents of the register serve as inputs to the internal state machine. The state machine outputs dictate the function of the device.

The command register itself does not occupy any addressable memory location. The register is a latch used to store the commands, along with the address and data information needed to execute the command. The command register is written by bringing $\overline{WE}$ to V$_{IL}$, while $\overline{CE}$ is at V$_{IL}$ and $\overline{OE}$ is at V$_{IH}$. Addresses are latched on the falling edge of $\overline{WE}$ or $\overline{CE}$, whichever happens later; while data is latched on the rising edge of $\overline{WE}$ or $\overline{CE}$, whichever happens first. Standard microprocessor write timings are used.

Refer to AC Write Characteristics and the Erase/Programming Waveforms for specific timing parameters.

Sector Protection

The MBM29F800TA/BA features hardware sector protection. This feature will disable both program and erase operations in any number of sectors (0 through 18). The sector protection feature is enabled using programming equipment at the user's site. The device is shipped with all sectors unprotected.

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To activate this mode, the programming equipment must force V_{ID} on address pin A_9 and control pin $\overline{OE}$, (suggest $V_{ID} = 11.5V$), $\overline{CE} = V_{IL}$, and $A_6 = V_{IL}$. The sector addresses (A_{18}, A_{17}, A_{16}, A_{15}, A_{14}, A_{13}, and A_{12}) should be set to the sector to be protected. Tables 5 and 6 define the sector address for each of the nineteen (19) individual sectors. Programming of the protection circuitry begins on the falling edge of the $\overline{WE}$ pulse and is terminated with the rising edge of the same. Sector addresses must be held constant during the $\overline{WE}$ pulse. See Figures 16 and 23 for sector protection waveforms and algorithm.

To verify programming of the protection circuitry, the programming equipment must force V_{ID} on address pin A_9 with $\overline{CE}$ and $\overline{OE}$ at V_{IL} and $\overline{WE}$ at V_{IH}. Scanning the sector addresses (A_{18}, A_{17}, A_{16}, A_{15}, A_{14}, A_{13}, and A_{12}) while (A_6, A_1, A_0) = (0, 1, 0) will produce a logical "1" code at device output DQ_0 for a protected sector. Otherwise the devices will read 00H for unprotected sector. In this mode, the lower order addresses, except for A_0, A_1, and A_6 are DON'T CARES. Address locations with $A_1 = V_{IL}$ are reserved for Autoselect manufacturer and device codes. A_{-1} requires to apply to V_{IL} on byte mode.

It is also possible to determine if a sector is protected in the system by writing an Autoselect command. Performing a read operation at the address location XX02H, where the higher order addresses (A_{18}, A_{17}, A_{16}, A_{15}, A_{14}, A_{13}, and A_{12}) are the desired sector address will produce a logical "1" at DQ_0 for a protected sector. See Tables 4.1 and 4.2 for Autoselect codes.

Temporary Sector Unprotection

This feature allows temporary unprotection of previously protected sectors of the MBM29F800TA/BA device in order to change data. The Sector Unprotection mode is activated by setting the $\overline{RESET}$ pin to high voltage (12 V). During this mode, formerly protected sectors can be programmed or erased by selecting the sector addresses. Once the 12 V is taken away from the $\overline{RESET}$ pin, all the previously protected sectors will be protected again. Refer to Figures 17 and 24.

Table 5   Sector Address Tables (MBM29F800TA)

Sector Address	A_{18}	A_{17}	A_{16}	A_{15}	A_{14}	A_{13}	A_{12}	Address Range
SA0	0	0	0	0	X	X	X	00000H to 0FFFFH
SA1	0	0	0	1	X	X	X	10000H to 1FFFFH
SA2	0	0	1	0	X	X	X	20000H to 2FFFFH
SA3	0	0	1	1	X	X	X	30000H to 3FFFFH
SA4	0	1	0	0	X	X	X	40000H to 4FFFFH
SA5	0	1	0	1	X	X	X	50000H to 5FFFFH
SA6	0	1	1	0	X	X	X	60000H to 6FFFFH
SA7	0	1	1	1	X	X	X	70000H to 7FFFFH
SA8	1	0	0	0	X	X	X	80000H to 8FFFFH
SA9	1	0	0	1	X	X	X	90000H to 9FFFFH
SA10	1	0	1	0	X	X	X	A0000H to AFFFFH
SA11	1	0	1	1	X	X	X	B0000H to BFFFFH
SA12	1	1	0	0	X	X	X	C0000H to CFFFFH
SA13	1	1	0	1	X	X	X	D0000H to DFFFFH
SA14	1	1	1	0	X	X	X	E0000H to EFFFFH
SA15	1	1	1	1	0	X	X	F0000H to F7FFFH
SA16	1	1	1	1	1	0	0	F8000H to F9FFFH
SA17	1	1	1	1	1	0	1	FA000H to FBFFFH
SA18	1	1	1	1	1	1	X	FC000H to FFFFFH

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Table 6   Sector Address Tables (MBM29F800BA)

Sector Address	A_{18}	A_{17}	A_{16}	A_{15}	A_{14}	A_{13}	A_{12}	Address Range
SA0	0	0	0	0	0	0	X	00000H to 03FFFH
SA1	0	0	0	0	0	1	0	04000H to 05FFFH
SA2	0	0	0	0	0	1	1	06000H to 07FFFH
SA3	0	0	0	0	1	X	X	08000H to 0FFFFH
SA4	0	0	0	1	X	X	X	10000H to 1FFFFH
SA5	0	0	1	0	X	X	X	20000H to 2FFFFH
SA6	0	0	1	1	X	X	X	30000H to 3FFFFH
SA7	0	1	0	0	X	X	X	40000H to 4FFFFH
SA8	0	1	0	1	X	X	X	50000H to 5FFFFH
SA9	0	1	1	0	X	X	X	60000H to 6FFFFH
SA10	0	1	1	1	X	X	X	70000H to 7FFFFH
SA11	1	0	0	0	X	X	X	80000H to 8FFFFH
SA12	1	0	0	1	X	X	X	90000H to 9FFFFH
SA13	1	0	1	0	X	X	X	A0000H to AFFFFH
SA14	1	0	1	1	X	X	X	B0000H to BFFFFH
SA15	1	1	0	0	X	X	X	C0000H to CFFFFH
SA16	1	1	0	1	X	X	X	D0000H to DFFFFH
SA17	1	1	1	0	X	X	X	E0000H to EFFFFH
SA18	1	1	1	1	X	X	X	F0000H to FFFFFH

Table 7   MBM29F800TA/BA Command Definitions

Command Sequence		Bus Write Cycles Req'd	First Bus Write Cycle		Second Bus Write Cycle		Third Bus Write Cycle		Fourth Bus Read/Write Cycle		Fifth Bus Write Cycle		Sixth Bus Write Cycle	
			Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data
Read/Reset	Word	1	XXXH	F0H	—	—	—	—	—	—	—	—	—	—
	Byte													
Read/Reset	Word	3	555H	AAH	2AAH	55H	555H	F0H	RA	RD	—	—	—	—
	Byte		AAAH		555H		AAAH							
Autoselect	Word	3	555H	AAH	2AAH	55H	555H	90H	—	—	—	—	—	—
	Byte		AAAH		555H		AAAH							
Byte/Word Program	Word	4	555H	AAH	2AAH	55H	555H	A0H	PA	PD	—	—	—	—
	Byte		AAAH		555H		AAAH							
Chip Erase	Word	6	555H	AAH	2AAH	55H	555H	80H	555H	AAH	2AAH	55H	555H	10H
	Byte		AAAH		555H		AAAH		AAAH		555H		AAAH	
Sector Erase	Word	6	555H	AAH	2AAH	55H	555H	80H	555H	AAH	2AAH	55H	SA	30H
	Byte		AAAH		555H		AAAH		AAAH		555H			
Sector Erase Suspend		Erase can be suspended during sector erase with Addr ("H" or "L"). Data (B0H)												
Sector Erase Resume		Erase can be resumed after suspend with Addr ("H" or "L"). Data (30H)												

Notes: 1. Address bits A_{18} to A_{11} = X = "H" or "L" for all address commands except or Program Address (PA) and Sector Address (SA).
2. Bus operations are defined in Tables 2 and 3.
3. RA = Address of the memory location to be read.
PA = Address of the memory location to be programmed. Addresses are latched on the falling edge of the $\overline{WE}$ pulse.
SA = Address of the sector to be erased. The combination of A_{18}, A_{17}, A_{16}, A_{15}, A_{14}, A_{13}, and A_{12} will uniquely select any sector.
4. RD = Data read from location RA during read operation.
PD = Data to be programmed at location PA. Data is latched on the falling edge of $\overline{WE}$.
5. The system should generate the following address patterns:
Word Mode: 555H or 2AAH to addresses A_0 to A_{10}
Byte Mode: AAAH or 555H to addresses A_{-1} to A_{10}
6. Both Read/Reset commands are functionally equivalent, resetting the device to the read mode.

Command Definitions

Device operations are selected by writing specific address and data sequences into the command register. Writing incorrect address and data values or writing them in the improper sequence will reset the device to the read mode. Table 7 defines the valid register command sequences. Note that the Erase Suspend (B0H) and Erase Resume (30H) commands are valid only while the Sector Erase operation is in progress. Moreover both Read/Reset commands are functionally equivalent, resetting the device to the read mode. Please note that commands are always written at DQ_0 to DQ_7 and DQ_8 to DQ_{15} bits are ignored.

Read/Reset Command

The read or eset operation is initiated by writing the Read/Reset command sequence into the command register. Microprocessor read cycles retrieve array data from the memory. The devices remain enabled for reads until the command register contents are altered.

The device will automatically power-up in the read/reset state. In this case, a command sequence is not required to read data. Standard microprocessor read cycles will retrieve array data. This default value ensures that no spurious alteration of the memory content occurs during the power transition. Refer to the AC Read Characteristics and Waveforms for the specific timing parameters.

Autoselect Command

Flash memories are intended for use in applications where the local CPU alters memory contents. As such, manufacture and device codes must be accessible while the devices reside in the target system. PROM programmers typically access the signature codes by raising A_9 to a high voltage. However, multiplexing high voltage onto the address lines is not generally desired system design practice.

The device contains an Autoselect command operation to supplement traditional PROM programming methodology. The operation is initiated by writing the Autoselect command sequence into the command register. Following the command write, a read cycle from address XX00H retrieves the manufacture code of 04H. A read cycle from address XX01H for ×16 (XX02H for ×8) returns the device code (MBM29F800TA = D6H and MBM29F800BA = 58H for ×8 mode; MBM29F800TA = 22D6H and MBM29F800BA = 2258H for ×16 mode). (See Tables 4.1 and 4.2.)

All manufacturer and device codes will exhibit odd parity with DQ_7 defined as the parity bit.
Sector state (protection or unprotection) will be informed by address XX02H for ×16 (XX04H for ×8).
Scanning the sector addresses (A_{18}, A_{17}, A_{16}, A_{15}, A_{14}, A_{13}, and A_{12}) while (A_6, A_1, A_0) = (0, 1, 0) will produce a logical "1" at device output DQ_0 for a protected sector. The programming verification should be perform margin mode on the protected sector (See Tables 2 and 3).

To terminate the operation, it is necessary to write the Read/Reset command sequence into the register, and also to write the Autoselect command during the operation, execute it after writing Read/Reset command sequence.

Byte/Word Programming

The device is programmed on a byte-by-byte (or word-by-word) basis. Programming is a four bus cycle operation. There are two "unlock" write cycles. These are followed by the program set-up command and data write cycles. Addresses are latched on the falling edge of $\overline{CE}$ or $\overline{WE}$, whichever happens later and the data is latched on the rising edge of $\overline{CE}$ or $\overline{WE}$, whichever happens first. The rising edge of $\overline{CE}$ or $\overline{WE}$ (whichever happens first) begins programming. Upon executing the Embedded Program™ Algorithm command sequence, the system is not required to provide further controls or timings. The device will automatically provide adequate internally generated program pulses and verify the programmed cell margin.

The automatic programming operation is completed when the data on DQ_7 is equivalent to data written to this bit at which time the devices return to the read mode and addresses are no longer latched (See Table 8, Hardware Sequence Flags) Therefore, the devices require that a valid address to the devices be supplied by the system at this particular instance of time. Hence, $\overline{Data}$ Polling must be performed at the memory location which is being programmed.

Any commands written to the chip during this period will be ignored. If hardware reset occurs during the programming operation, it is impossible to guarantee the data are being written.

Programming is allowed in any sequence and across sector boundaries. Beware that a data "0" cannot be programmed back to a "1". Attempting to do so may either hang up the device or result in an apparent success according to the data polling algorithm but a read from Read/Reset mode will show that the data is still "0". Only erase operations can convert "0"s to "1"s.

Figure 19 illustrates the Embedded Programming Algorithm™ using typical command strings and bus operations.

Chip Erase

Chip erase is a six bus cycle operation. There are two "unlock" write cycles. These are followed by writing the "set-up" command. Two more "unlock" write cycles are then followed by the chip erase command.

Chip erase does not require the user to program the device prior to erase. Upon executing the Embedded Erase™ Algorithm command sequence the device will automatically program and verify the entire memory for an all zero data pattern prior to electrical erase. The system is not required to provide any controls or timings during these operations.

The automatic erase begins on the rising edge of the last $\overline{WE}$ pulse in the command sequence and terminates when the data on DQ$_7$ is "1" (see Write Operation Status section) at which time the device returns to read the mode.

Figure 20 illustrates the Embedded Erase Algorithm using typical command strings and bus operations.

Sector Erase

Sector erase is a six bus cycle operation. There are two "unlock" write cycles. These are followed by writing the "set-up" command. Two more "unlock" write cycles are then followed by the Sector Erase command. The sector address (any address location within the desired sector) is latched on the falling edge of $\overline{WE}$, while the command (Data = 30H) is latched on the rising edge of $\overline{WE}$. After time-out of 50 μs from the rising edge of the last sector erase command, the sector erase operation will begin.

Multiple sectors may be erased concurrently by writing the six bus cycle operations on Table 7. This sequence is followed with writes of the Sector Erase command to addresses in other sectors desired to be concurrently erased. The time between writes must be less than 50 μs otherwise that command will not be accepted and erasure will start. It is recommended that processor interrupts be disabled during this time to guarantee this condition. The interrupts can be re-enabled after the last Sector Erase command is written. A time-out of 50 μs from the rising edge of the last $\overline{WE}$ will initiate the execution of the Sector Erase command(s). If another falling edge of the $\overline{WE}$ occurs within the 50 μs time-out window the timer is reset. (Monitor DQ$_3$ to determine if the sector erase timer window is still open, see section DQ$_3$, Sector Erase Timer.) Any command other than Sector Erase or Erase Suspend during this time-out period will reset the devices to the read mode, ignoring the previous command string. Resetting the device once execution has begun will corrupt the data in that sector. In that case, restart the erase on those sectors and allow them to complete. (Refer to the Write Operation Status section for Sector Erase Timer operation.) Loading the sector erase buffer may be done in any sequence and with any number of sectors (0 to 18).

Sector erase does not require the user to program the devices prior to erase. The device automatically programs all memory locations in the sector(s) to be erased prior to electrical erase. When erasing a sector or sectors the remaining unselected sectors are not affected. The system is not required to provide any controls or timings during these operations.

The automatic sector erase begins after the 50 μs time out from the rising edge of the $\overline{WE}$ pulse for the last sector erase command pulse and terminates when the data on DQ$_7$ is "1" (see Write Operation Status section) at which time the device returns to the read mode. $\overline{Data}$ polling must be performed at an address within any of the sectors being erased.

Figure 20 illustrates the Embedded Erase Algorithm using typical command strings and bus operations.

Erase Suspend

The Erase Suspend command allows the user to interrupt a Sector Erase operation and then perform data reads from or programs to a sector not being erased. This command is applicable ONLY during the Sector Erase operation which includes the time-out period for sector erase. The Erase Suspend command will be ignored if written during the Chip Erase operation or Embedded Program Algorithm. Writting the Erase Suspend command during the Sector Erase time-out results in immediate termination of the time-out period and suspension of the erase operation.

Writing the Erase Resume command resumes the erase operation. The addresses are "don't cares" when writing the Erase Suspend or Erase Resume command.

When the Erase Suspend command is written during the Sector Erase operation, the device will take a maximum of 20 μs to suspend the erase operation. When the device has entered the erase-suspended mode, the RY/$\overline{\text{BY}}$ output pin and the DQ_7 bit will be at logic "1", and DQ_6 will stop toggling. The user must use the address of the erasing sector for reading DQ_6 and DQ_7 to determine if the erase operation has been suspended. Further writes of the Erase Suspend command are ignored.

When the erase operation has been suspended, the device defaults to the erase-suspend-read mode. Reading data in this mode is the same as reading from the standard read mode except that the data must be read from sectors that have not been erase-suspended. Successively reading from the erase-suspended sector while the device is in the erase-suspend-read mode will cause DQ_2 to toggle. (See the section on DQ_2).

After entering the erase-suspend-read mode, the user can program the device by writing the appropriate command sequence for Program. This Program mode is known as the erase-suspend-program mode. Again, programming in this mode is the same as programming in the regular Program mode except that the data must be programmed to sectors that are not erase-suspended. Successively reading from the erase-suspended sector while the device is in the erase-suspend-program mode will cause DQ_2 to toggle. The end of the erase-suspended Program operation is detected by the RY/$\overline{\text{BY}}$ output pin, $\overline{\text{Data}}$ polling of DQ_7, or by the Toggle Bit I (DQ_6) which is the same as the regular Program operation. Note that DQ_7 must be read from the Program address while DQ_6 can be read from any address.

To resume the operation of Sector Erase, the Resume command (30H) should be written. Any further writes of the Resume command at this point will be ignored. Another Erase Suspend command can be written after the chip has resumed erasing.

Write Operation Status

Table 8   Hardware Sequence Flags

Status			DQ_7	DQ_6	DQ_5	DQ_3	DQ_2
In Progress	Embedded Program Algorithm		$\overline{DQ_7}$	Toggle	0	0	1
	Embedded Erase Algorithm		0	Toggle	0	1	Toggle
	Erase Suspended Mode	Erase Suspend Read (Erase Suspended Sector)	1	1	0	0	Toggle
		Erase Suspend Read (Non-Erase Suspended Sector)	Data	Data	Data	Data	Data
		Erase Suspend Program (Non-Erase Suspended Sector)	$\overline{DQ_7}$	Toggle (Note 1)	0	0	1 (Note 2)
Exceeded Time Limits	Embedded Program Algorithm		$\overline{DQ_7}$	Toggle	1	0	1
	Embedded Erase Algorithm		0	Toggle	1	1	N/A
	Erase Suspended Mode	Erase Suspend Program (Non-Erase Suspended Sector)	$\overline{DQ_7}$	Toggle	1	0	N/A

Notes: 1. Performing successive read operations from any address will cause DQ_6 to toggle.
2. Reading the byte address being programmed while in the erase-suspend program mode will indicate logic "1" at the DQ_2 bit. However, successive reads from the erase-suspended sector will cause DQ_2 to toggle.
3. DQ_0 and DQ_1 are reserve pins for future use. DQ_4 is Fujitsu internal use only.
4. DQ_8 to DQ_{15} are "DON'T CARES" because there is for $\times$ 16 mode.

DQ$_7$

$\overline{\text{Data}}$ Polling

The MBM29F800TA/BA device feature $\overline{\text{Data}}$ Polling as a method to indicate to the host that the Embedded Algorithms are in progress or completed. During the Embedded Program Algorithm an attempt to read the device will produce the complement of the data last written to DQ$_7$. Upon completion of the Embedded Program Algorithm, an attempt to read the device will produce the true data last written to DQ$_7$. During the Embedded Erase Algorithm, an attempt to read the device will produce a "0" at the DQ$_7$ output. Upon completion of the Embedded Erase Algorithm an attempt to read the device will produce a "1" at the DQ$_7$ output. The flowchart for $\overline{\text{Data}}$ Polling (DQ$_7$) is shown in Figure 21.

For chip erase and sector erase, the $\overline{\text{Data}}$ Polling is valid after the rising edge of the sixth $\overline{\text{WE}}$ pulse in the six write pulse sequence. $\overline{\text{Data}}$ Polling must be performed at sector address within any of the sectors being erased and not a protected sector. Otherwise, the status may not be valid. Once the Embedded Algorithm operation is close to being completed, the MBM29F800TA/BA data pins (DQ$_7$) may change asynchronously while the output enable ($\overline{\text{OE}}$) is asserted low. This means that the device is driving status information on DQ$_7$ at one instant of time and then that byte's valid data at the next instant of time. Depending on when the system samples the DQ$_7$ output, it may read the status or valid data. Even if the device has completed the Embedded Algorithm operation and DQ$_7$ has a valid data, the data outputs on DQ$_0$ to DQ$_6$ may be still invalid. The valid data on DQ$_0$ to DQ$_7$ will be read on the successive read attempts.

The $\overline{\text{Data}}$ Polling feature is only active during the Embedded Programming Algorithm, Embedded Erase Algorithm or sector erase time-out (See Table 8).

See Figure 9 for the $\overline{\text{Data}}$ Polling timing specifications and diagrams.

DQ$_6$

Toggle Bit I

The MBM29F800TA/BA also feature the "Toggle Bit I" as a method to indicate to the host system that the Embedded Algorithms are in progress or completed.

During an Embedded Program or Erase Algorithm cycle, successive attempts to read ($\overline{\text{OE}}$ toggling) data from the device will result in DQ$_6$ toggling between one and zero. Once the Embedded Program or Erase Algorithm cycle is completed, DQ$_6$ will stop toggling and valid data will be read on the next successive attempts. During programming, the Toggle Bit I is valid after the rising edge of the fourth $\overline{\text{WE}}$ pulse in the four write pulse sequence. For chip erase and sector erase, the Toggle Bit I is valid after the rising edge of the sixth $\overline{\text{WE}}$ pulse in the six write pulse sequence. The Toggle Bit I is active during the sector time out.

In programming, if the sector being written to is protected, the toggle bit I will toggle for about 2 µs and then stop toggling without the data having changed. In erase, the device will erase all the selected sectors except for the ones that are protected. If all selected sectors are protected, the chip will toggle the toggle bit for about 100 µs and then drop back into read mode, having changed none of the data.

Either $\overline{\text{CE}}$ or $\overline{\text{OE}}$ toggling will cause the DQ$_6$ to toggle. In addition, an Erase Suspend/Resume command will cause the DQ$_6$ to toggle.

See Figure 10 for the Toggle Bit I timing specifications and diagrams.

DQ$_5$

Exceeded Timing Limits

DQ$_5$ will indicate if the program or erase time has exceeded the specified limits (internal pulse count). Under these conditions DQ$_5$ will produce a "1". This is a failure condition which indicates that the program or erase cycle was not successfully completed. $\overline{\text{Data}}$ Polling is the only operating function of the devices under this condition. The $\overline{\text{CE}}$ circuit will partially power down the device under these conditions (to approximately 2 mA). The $\overline{\text{OE}}$ and $\overline{\text{WE}}$ pins will control the output disable functions as described in Tables 2 and 3.

The DQ_5 failure condition may also appear if a user tries to program a non blank location without erasing. In this case the device locks out and never complete the Embedded Algorithm operation. Hence, the system never reads a valid data on DQ_7 bit and DQ_6 never stops toggling. Once the device has exceeded timing limits, the DQ_5 bit will indicate a "1." Please note that this is not a device failure condition since the device was incorrectly used. If this occurs, rest the device with command sequence.

DQ_3

Sector Erase Timer

After the completion of the initial sector erase command sequence the sector erase time-out will begin. DQ_3 will remain low until the time-out is complete. $\overline{Data}$ Polling and Toggle Bit are valid after the initial sector erase command sequence.

If $\overline{Data}$ Polling or the Toggle Bit I indicates the device has been written with a valid erase command, DQ_3 may be used to determine if the sector erase timer window is still open. If DQ_3 is high ("1") the internally controlled erase cycle has begun; attempts to write subsequent commands to the device will be ignored until the erase operation is completed as indicated by $\overline{Data}$ Polling or Toggle Bit I. If DQ_3 is low ("0"), the device will accept additional sector erase commands. To insure the command has been accepted, the system software should check the status of DQ_3 prior to and following each subsequent sector erase command. If DQ_3 were high on the second status check, the command may not have been accepted.

Refer to Table 8: Hardware Sequence Flags.

DQ_2

Toggle Bit II

This toggle bit II, along with DQ_6, can be used to determine whether the device is in the Embedded Erase Algorithm or in Erase Suspend.

Successive reads from the erasing sector will cause DQ_2 to toggle during the Embedded Erase Algorithm. If the device is in the erase-suspended-read mode, successive reads from the erase-suspended sector will cause DQ_2 to toggle. When the device is in the erase-suspended-program mode, successive reads from the byte address of the non-erase suspended sector will indicate a logic "1" at the DQ_2 bit.

DQ_6 is different from DQ_2 in that DQ_6 toggles only when the standard program or Erase, or Erase Suspend Program operation is in progress. The behavior of these two status bits, along with that of DQ_7, is summarized as follows:

Mode	DQ_7	DQ_6	DQ_2
Program	$\overline{DQ_7}$	toggles	1
Erase	0	toggles	toggles
Erase Suspend Read (Erase-Suspended Sector) (Note 1)	1	1	toggles
Erase Suspend Program	$\overline{DQ_7}$ (Note 2)	toggles	1 (Note 2)

Notes: 1. These status flags apply when outputs are read from a sector that has been erase-suspended.
2. These status flags apply when outputs are read from the byte address of the non-erase suspended sector.

For example, DQ_2 and DQ_6 can be used together to determine the erase-suspend-read mode (DQ_2 toggles while DQ_6 does not). See also Table 8 and Figure 22.

Furthermore, DQ_2 can also be used to determine which sector is being erased. When the device is in the erase mode, DQ_2 toggles if this bit is read from the erasing sector.

RY/$\overline{\text{BY}}$

Ready/Busy

The MBM29F800TA/BA provides a RY/$\overline{\text{BY}}$ open-drain output pin as a way to indicate to the host system that the Embedded Algorithms are either in progress or has been completed. If the output is low, the device is busy with either a program or erase operation. If the output is high, the device is ready to accept any read/write or erase operation. When the RY/$\overline{\text{BY}}$ pin is low, the device will not accept any additional program or erase commands. If the MBM29F800TA/BA is placed in an Erase Suspend mode, the RY/$\overline{\text{BY}}$ output will be high. Also, since this is an open drain output, many RY/$\overline{\text{BY}}$ pins can be tied together in parallel with a pull up resistor to V_{CC}.

During programming, the RY/$\overline{\text{BY}}$ pin is driven low after the rising edge of the fourth $\overline{\text{WE}}$ pulse. During an erase operation, the RY/$\overline{\text{BY}}$ pin is driven low after the rising edge of the sixth $\overline{\text{WE}}$ pulse. The RY/$\overline{\text{BY}}$ pin will indicate a busy condition during the $\overline{\text{RESET}}$ pulse. Refer to Figure 11 and 12 for a detailed timing diagram.

Since this is an open-drain output, several RY/$\overline{\text{BY}}$ pins can be tied together in parallel with a pull-up resistor to V_{CC}.

$\overline{\text{RESET}}$

Hardware Reset

The MBM29F800TA/BA device may be reset by driving the $\overline{\text{RESET}}$ pin to V_{IL}. The $\overline{\text{RESET}}$ pin has a pulse requirement and has to be kept low (V_{IL}) for at least 500 ns in order to properly reset the internal state machine. Any operation in the process of being executed will be terminated and the internal state machine will be reset to the read mode 20 μs after the $\overline{\text{RESET}}$ pin is driven low. Furthermore, once the $\overline{\text{RESET}}$ pin goes high, the device requires time of t_{RH} before it will allow read access. When the $\overline{\text{RESET}}$ pin is low, the device will be in the standby mode for the duration of the pulse and all the data output pins will be tri-stated. If a hardware reset occurs during a program or erase operation, the data at that particular location will be corrupted. Please note that the RY/$\overline{\text{BY}}$ output signal should be ignored during the $\overline{\text{RESET}}$ pulse. Refer to Figure 12 for the timing diagram. Refer to Temporary Sector Unprotection for additional functionality.

If hardware reset occurs during Embedded Erase Algorithm, there is a possibility that the erasing sector(s) cannot be used.

Byte/Word Configuration

The $\overline{\text{BYTE}}$ pin selects the byte (8-bit) mode or word (16-bit) mode for the MBM29F800TA/BA device. When this pin is driven high, the device operates in the word (16-bit) mode. The data is read and programmed at DQ_0 to DQ_{15}. When this pin is driven low, the device operates in byte (8-bit) mode. Under this mode, the DQ_{15}/A$_{-1}$ pin becomes the lowest address bit and DQ_8 to DQ_{14} bits are tri-stated. However, the command bus cycle is always an 8-bit operation and hence commands are written at DQ_0 to DQ_7 and the DQ_8 to DQ_{15} bits are ignored. Refer to Figures 13, 14 and 15 for the timing diagram.

Data Protection

The MBM29F800TA/BA are designed to offer protection against accidental erasure or programming caused by spurious system level signals that may exist during power transitions. During power up the device automatically resets the internal state machine in the read mode. Also, with its control register architecture, alteration of the memory contents only occurs after successful completion of specific multi-bus cycle command sequences.

The device also incorporate several features to prevent inadvertent write cycles resulting form V_{CC} power-up and power-down transitions or system noise.

Low V_{CC} Write Inhibit

To avoid initiation of a write cycle during V_{CC} power-up and power-down, a write cycle is locked out for V_{CC} less than 3.2 V (typically 3.7 V). If $V_{CC} < V_{LKO}$, the command register is disabled and all internal program/erase circuits are disabled. Under this condition the device will reset to the read mode. Subsequent writes will be ignored until the V_{CC} level is greater than V_{LKO}. It is the users responsibility to ensure that the control pins are logically correct to prevent unintentional writes when V_{CC} is above 3.2 V.

If Embedded Erase Algorithm is interrupted, there is possibility that the erasing sector(s) cannot be used.

Write Pulse "Glitch" Protection

Noise pulses of less than 5 ns (typical) on $\overline{OE}$, $\overline{CE}$, or $\overline{WE}$ will not initiate a write cycle.

Logical Inhibit

Writing is inhibited by holding any one of $\overline{OE} = V_{IL}$, $\overline{CE} = V_{IH}$, or $\overline{WE} = V_{IH}$. To initiate a write cycle $\overline{CE}$ and $\overline{WE}$ must be a logical zero while $\overline{OE}$ is a logical one.

Power-Up Write Inhibit

Power-up of the device with $\overline{WE} = \overline{CE} = V_{IL}$ and $\overline{OE} = V_{IH}$ will not accept commands on the rising edge of $\overline{WE}$. The internal state machine is automatically reset to the read mode on power-up.

■ ABSOLUTE MAXIMUM RATINGS

Storage Temperature ....−55°C to +125°C
Ambient Temperature with Power Applied ....−40°C to +85°C
Voltage with respect to Ground All pins except A_9, $\overline{OE}$, and $\overline{RESET}$ (Note 1) ....−2.0 V to +7.0 V
V_{CC} (Note 1) ....−2.0 V to +7.0 V
A_9, $\overline{OE}$, and $\overline{RESET}$ (Note 2) ....−2.0 V to +13.5 V

Notes: 1. Minimum DC voltage on input or I/O pins are −0.5 V. During voltage transitions, inputs may negative
overshoot V_{SS} to −2.0 V for periods of up to 20 ns. Maximum DC voltage on output and I/O pins are
V_{CC} +0.5 V. During voltage transitions, outputs may positive overshoot to V_{CC} +2.0 V for periods of up
to 20 ns.
      2. Minimum DC input voltage on A_9, $\overline{OE}$, and $\overline{RESET}$ pins are −0.5 V. During voltage transitions, A_9, $\overline{OE}$,
and $\overline{RESET}$ pins may negative overshoot V_{SS} to −2.0 V for periods of up to 20 ns. Maximum DC input
voltage on A_9, $\overline{OE}$, and $\overline{RESET}$ pins are +13.0 V which may positive overshoot to +14.0 V for periods
of up to 20 ns. Voltage difference between input voltage and power supply. (V_{IN} - V_{CC}) do not exceed 9 V.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current,
temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING RANGES

Ambient Temperature (T_A) ....−40°C to +85°C
V_{CC} Supply Voltages
   MBM29F800TA/BA-55 ....+4.75 V to +5.25 V
   MBM29F800TA/BA-70/-90 ....+4.50 V to +5.50 V
Operating ranges define those limits between which the functionality of the devices are guaranteed.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the
semiconductor device. All of the device's electrical characteristics are warranted when the device is
operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation
outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on
the data sheet. Users considering application outside the listed conditions are advised to contact their
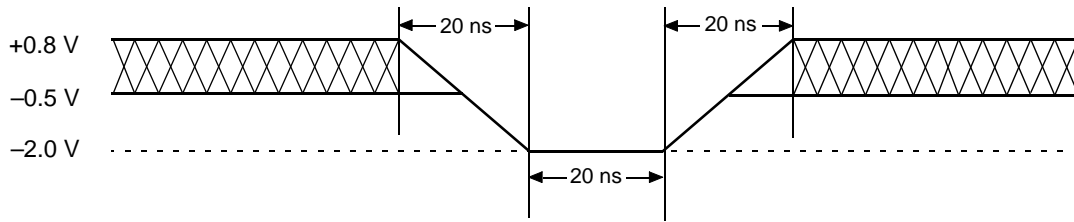FUJITSU representatives beforehand.

■ MAXIMUM OVERSHOOT

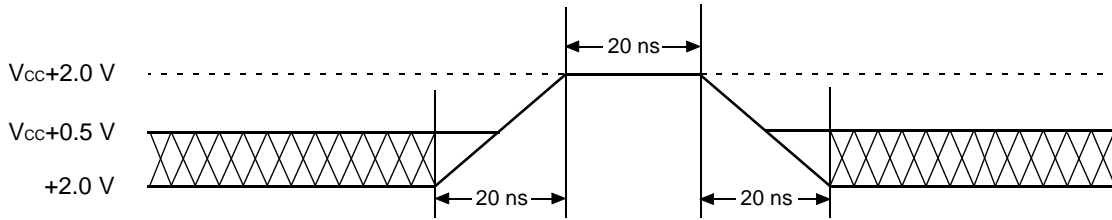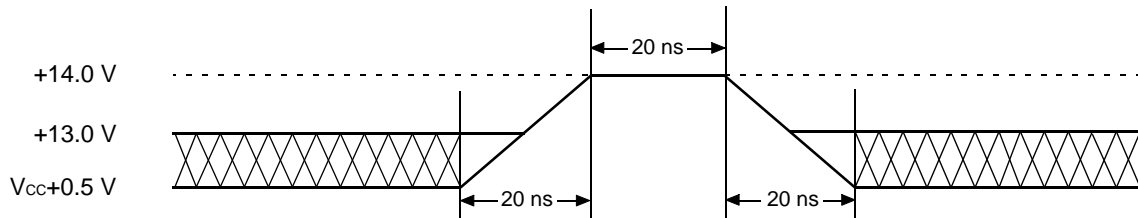Figure 1   Maximum Negative Overshoot Waveform

Figure 2   Maximum Positive Overshoot Waveform 1

Note: This waveform is applied for A$_9$, $\overline{OE}$, and $\overline{RESET}$.

Figure 3   Maximum Positive Overshoot Waveform 2

■ **DC CHARACTERISTICS**

Parameter Symbol	Parameter Description	Test Conditions		Min.	Max.	Unit
I_{LI}	Input Leakage Current	$V_{IN} = V_{SS}$ to V_{CC}, $V_{CC} = V_{CC}$ Max.		−1.0	+1.0	μA
I_{LO}	Output Leakage Current	$V_{OUT} = V_{SS}$ to V_{CC}, $V_{CC} = V_{CC}$ Max.		−1.0	+1.0	μA
I_{LIT}	A_9, $\overline{OE}$, $\overline{RESET}$ Inputs Leakage Current	$V_{CC} = V_{CC}$ Max. A_9, $\overline{OE}$, $\overline{RESET}$ = 12.5 V		—	50	μA
I_{CC1}	V_{CC} Active Current (Note 1)	$\overline{CE} = V_{IL}$, $\overline{OE} = V_{IH}$	Byte	—	38	mA
			Word		45	
I_{CC2}	V_{CC} Active Current (Note 2)	$\overline{CE} = V_{IL}$, $\overline{OE} = V_{IH}$		—	50	mA
I_{CC3}	V_{CC} Current (Standby)	$V_{CC} = V_{CC}$ Max., $\overline{CE} = V_{IH}$, $\overline{RESET} = V_{IH}$		—	1	mA
		$V_{CC} = V_{CC}$ Max., $\overline{CE} = V_{CC} \pm 0.3$ V, $\overline{RESET} = V_{CC} \pm 0.3$ V		—	5	μA
I_{CC4}	V_{CC} Current (Standby, Reset)	$V_{CC} = V_{CC}$ Max., $\overline{RESET} = V_{IL}$		—	1	mA
		$V_{CC} = V_{CC}$ Max., $\overline{RESET} = V_{SS} \pm 0.3$ V		—	5	μA
V_{IL}	Input Low Level	—		−0.5	0.8	V
V_{IH}	Input High Level	—		2.0	$V_{CC} + 0.5$	V
V_{ID}	Voltage for Autoselect and Sector Protection (A_9, $\overline{OE}$, $\overline{RESET}$) (Note 3, 4)	—		11.5	12.5	V
V_{OL}	Output Low Voltage Level	$I_{OL} = 5.8$mA, $V_{CC} = V_{CC}$ Min.		—	0.45	V
V_{OH1}	Output High Voltage Level	$I_{OH} = −2.5$ mA, $V_{CC} = V_{CC}$ Min.		2.4	—	V
V_{OH2}		$I_{OH} = −100$ μA		$V_{CC} − 0.4$	—	V
V_{LKO}	Low V_{CC} Lock-Out Voltage	—		3.2	4.2	V

Notes: 1. The I_{CC} current listed includes both the DC operating current and the frequency dependent component (at 6 MHz). The frequency component typically is 2 mA/MHz, with $\overline{OE}$ at V_{IH}.
2. I_{CC} active while Embedded Algorithm (program or erase) is in progress.
3. Applicable to sector protection function.
4. ($V_{ID} − V_{CC}$) do not exceed 9 V.

MBM29F800TA-55/-70/-90/MBM29F800BA-55/-70/-90

■ **AC CHARACTERISTICS**

• **Read Only Operations Characteristics**

Parameter Symbols		Description	Test Setup		MBM29F800TA/BA			Unit
JEDEC	Standard				-55 (Note1)	-70 (Note2)	-90 (Note2)	
t_{AVAV}	t_{RC}	Read Cycle Time	—	Min.	55	70	90	ns
t_{AVQV}	t_{ACC}	Address to Output Delay	$\overline{CE} = V_{IL}$ $\overline{OE} = V_{IL}$	Max.	55	70	90	ns
t_{ELQV}	t_{CE}	Chip Enable to Output Delay	$\overline{OE} = V_{IL}$	Max.	55	70	90	ns
t_{GLQV}	t_{OE}	Output Enable to Output Delay	—	Max.	30	30	40	ns
t_{EHQZ}	t_{DF}	Chip Enable to Output High-Z	—	Max.	15	20	20	ns
t_{GHQZ}	t_{DF}	Output Enable to Output High-Z	—	Max.	15	20	20	ns
t_{AXQX}	t_{OH}	Output Hold Time From Addresses, $\overline{CE}$ or $\overline{OE}$, Whichever Occurs First	—	Min.	0	0	0	ns
—	t_{READY}	$\overline{RESET}$ Pin Low to Read Mode	—	Max.	20	20	20	µs
—	t_{ELFL} t_{ELFH}	$\overline{CE}$ or $\overline{BYTE}$ Switching Low or High	—	Max.	5	5	5	ns

Note: 1. Test Conditions:
Output Load: 1 TTL gate and 30 pF
Input rise and fall times: 5 ns
Input pulse levels: 0.0 V to 3.0 V
Timing measurement reference level
　　　Input: 1.5 V
　　　Output: 1.5 V

Note: 2. Test Conditions:
Output Load: 1 TTL gate and 100 pF
Input rise and fall times: 5 ns
Input pulse levels: 0.45 V to 2.4 V
Timing measurement reference level
　　　Input: 0.8 V and 2.0 V
　　　Output: 0.8 V and 2.0 V
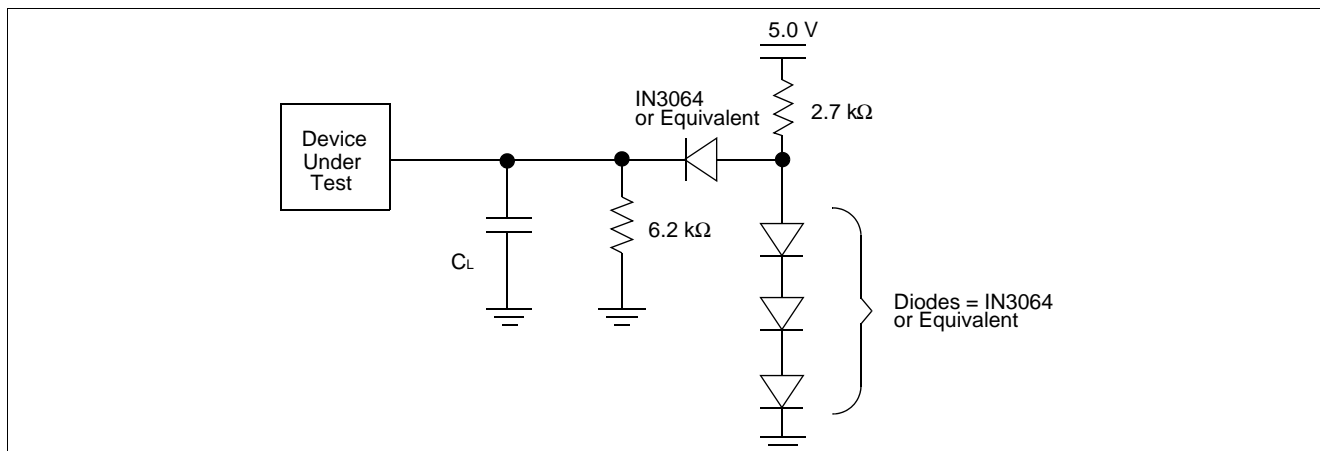
Notes: 1. C_L = 30 pF including jig capacitance (MBM29F800TA/BA-55)
　　　　　2. C_L = 100 pF including jig capacitance (MBM29F800TA/BA-70/-90)

Figure 4　Test Conditions

• **Write/Erase/Program Operations**

Parameter Symbols		Description		MBM28F800TA/BA			Unit
JEDEC	Standard			-55	-70	-90	
t_{AVAV}	t_{WC}	Write Cycle Time	Min.	55	70	90	ns
t_{AVWL}	t_{AS}	Address Setup Time	Min.	0	0	0	ns
t_{WLAX}	t_{AH}	Address Hold Time	Min.	40	45	45	ns
t_{DVWH}	t_{DS}	Data Setup Time	Min.	25	30	45	ns
t_{WHDX}	t_{DH}	Data Hold Time	Min.	0	0	0	ns
—	t_{OES}	Output Enable Setup Time	Min.	0	0	0	ns
—	t_{OEH}	Output Enable Hold Time — Read	Min.	0	0	0	ns
		Output Enable Hold Time — Toggle and $\overline{Data}$ Polling	Min.	10	10	10	ns
t_{GHWL}	t_{GHWL}	Read Recover Time Before Write	Min.	0	0	0	ns
t_{GHEL}	t_{GHEL}	Read Recover Time Before Write	Min.	0	0	0	ns
t_{ELWL}	t_{CS}	$\overline{CE}$ Setup Time	Min.	0	0	0	ns
t_{WLEL}	t_{WS}	$\overline{WE}$ Setup Time	Min.	0	0	0	ns
t_{WHEH}	t_{CH}	$\overline{CE}$ Hold Time	Min.	0	0	0	ns
t_{EHWH}	t_{WH}	$\overline{WE}$ Hold Time	Min.	0	0	0	ns
t_{WLWH}	t_{WP}	Write Pulse Width	Min.	30	35	45	ns
t_{ELEH}	t_{CP}	$\overline{CE}$ Pulse Width	Min.	30	35	45	ns
t_{WHWL}	t_{WPH}	Write Pulse Width High	Min.	20	20	20	ns
t_{EHEL}	t_{CPH}	$\overline{CE}$ Pulse Width High	Min.	20	20	20	ns
t_{WHWH1}	t_{WHWH1}	Byte Programming Operation	Typ.	8	8	8	µs
t_{WHWH2}	t_{WHWH2}	Sector Erase Operation (Note 1)	Typ.	1	1	1	sec
			Max.	8	8	8	sec
—	t_{VCS}	V_{CC} Setup Time	Min.	50	50	50	µs
—	t_{VIDR}	RiseTime to V_{ID}	Min.	500	500	500	ns
—	t_{VLHT}	Voltage Transition Time (Note 2)	Min.	4	4	4	µs
—	t_{WPP}	Write Pulse Width (Note 2)	Min.	100	100	100	µs
—	t_{OESP}	$\overline{OE}$ Setup Time to $\overline{WE}$ Active (Note 2)	Min.	4	4	4	µs
—	t_{CSP}	$\overline{CE}$ Setup Time to $\overline{WE}$ Active (Note 2)	Min.	4	4	4	µs
—	t_{RB}	Recover Time from RY/$\overline{BY}$	Min.	0	0	0	ns

(Continued)

(Continued)

Parameter Symbols		Description		MBM29F800TA/BA			Unit
JEDEC	Standard			-55	-70	-90	
—	t_{RP}	$\overline{RESET}$ Pulse Width	Min.	500	500	500	ns
—	t_{RH}	$\overline{RESET}$ Hold Time Before Read	Min.	50	50	50	ns
—	t_{FLQZ}	$\overline{BYTE}$ Switching Low to Output HIGH-Z	Max.	30	30	40	ns
—	t_{FHQV}	$\overline{BYTE}$ Switching High to Output Active	Min.	30	30	40	ns
—	t_{BUSY}	Program/Erase Valid to RY/$\overline{BY}$ Delay	Max.	55	70	90	ns
—	t_{EOE}	Delay Time from Embedded Output Enable	Max.	30	30	40	ns

Notes: 1. This does not include the preprogramming time.
2. These timing is for Sector Protection operation.

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■ SWITCHING WAVEFORMS

• **Key to Switching Waveforms**

WAVEFORM	INPUTS	OUTPUTS
	Must Be Steady	Will Be Steady
	May Change from H to L	Will Be Changing from H to L
	May Change from L to H	Will Be Changing from L to H
	"H" or "L" Any Change Permitted	Changing State Unknown
	Does Not Apply	Center Line is High-Impedance "Off" State
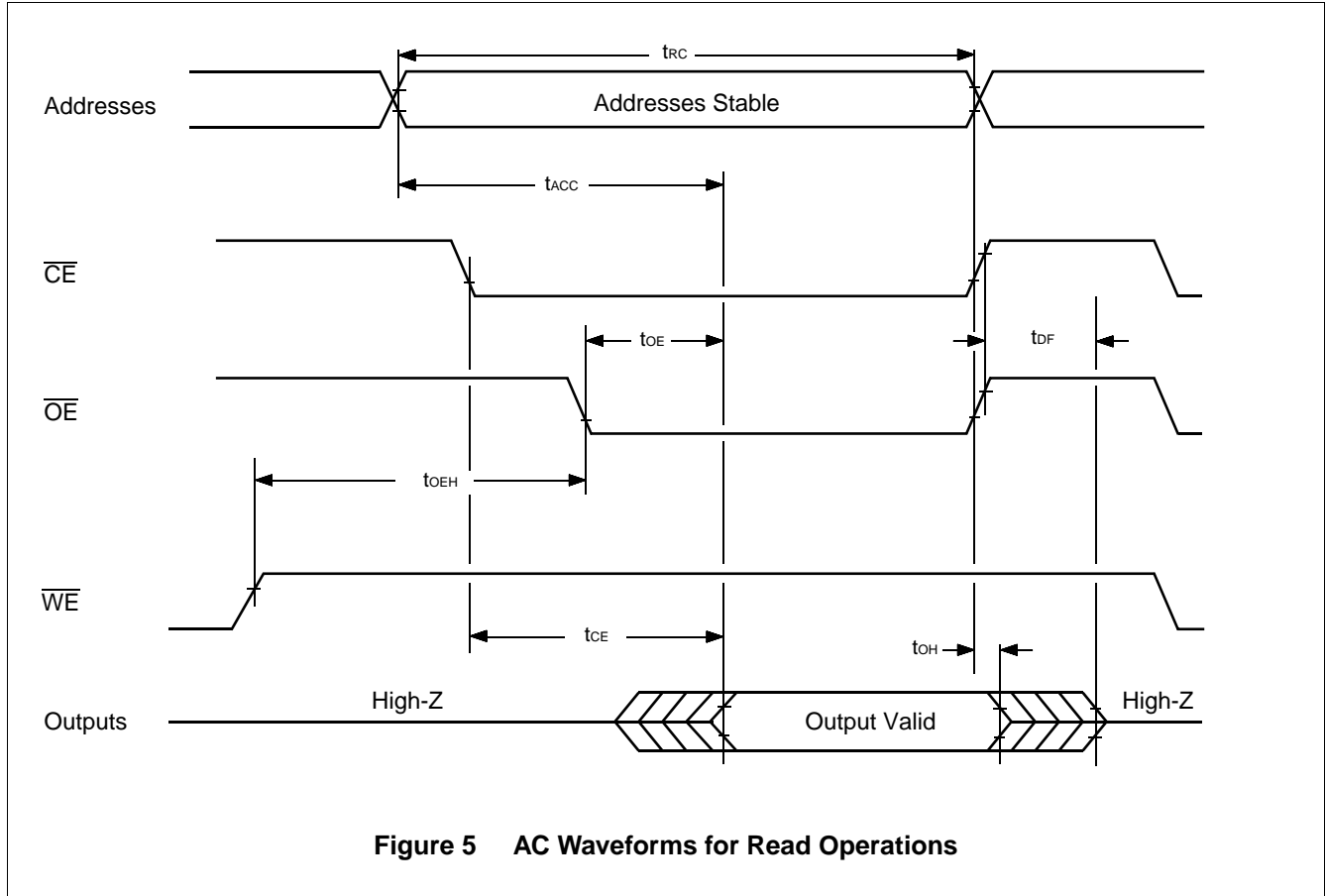
Figure 5   AC Waveforms for Read Operations
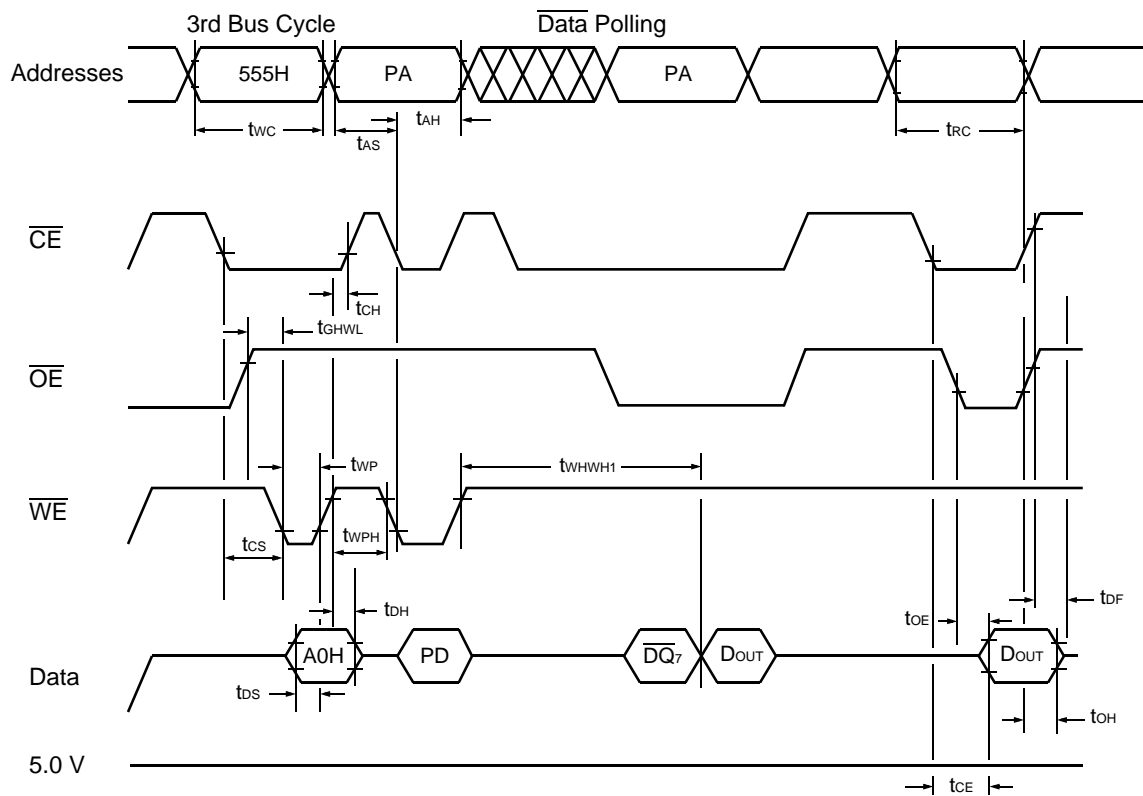
Notes: 1. PA is address of the memory location to be programmed
2. PD is data to be programmed at byte address.
3. $\overline{DQ_7}$ is the output of the complement of the data written to the device.
4. D_{OUT} is the output of the data written to the device.
5. Figure indicates last two bus cycles out of four bus cycle sequence.
6. These waveforms are for the × 16 mode.

Figure 6   AC Waveforms for Alternate $\overline{WE}$ Controlled Program Operations
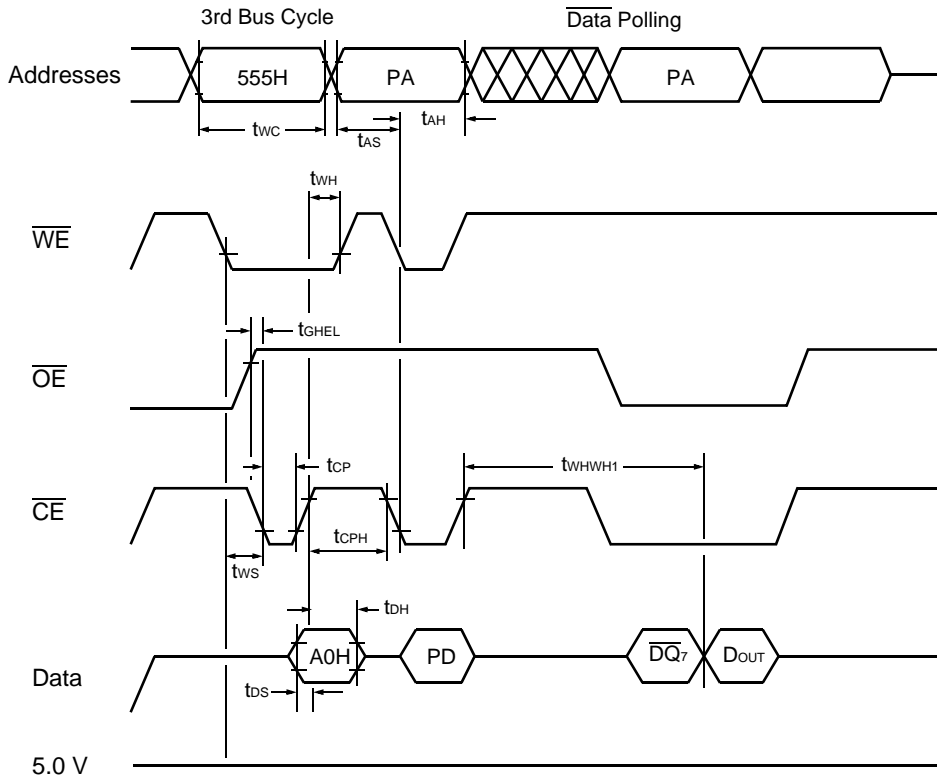
Notes: 1. PA is address of the memory location to be programmed.
2. PD is data to be programmed at byte address.
3. $\overline{DQ_7}$ is the output of the complement of the data written to the device.
4. D_{OUT} is the output of the data written to the device.
5. Figure indicates last two bus cycles out of four bus cycle sequence.
6. These waveforms are for the $\times 16$ mode. (The addresses differ from $\times 8$ mode.)

Figure 7   AC Waveforms for Alternate $\overline{CE}$ Controlled Program Operations
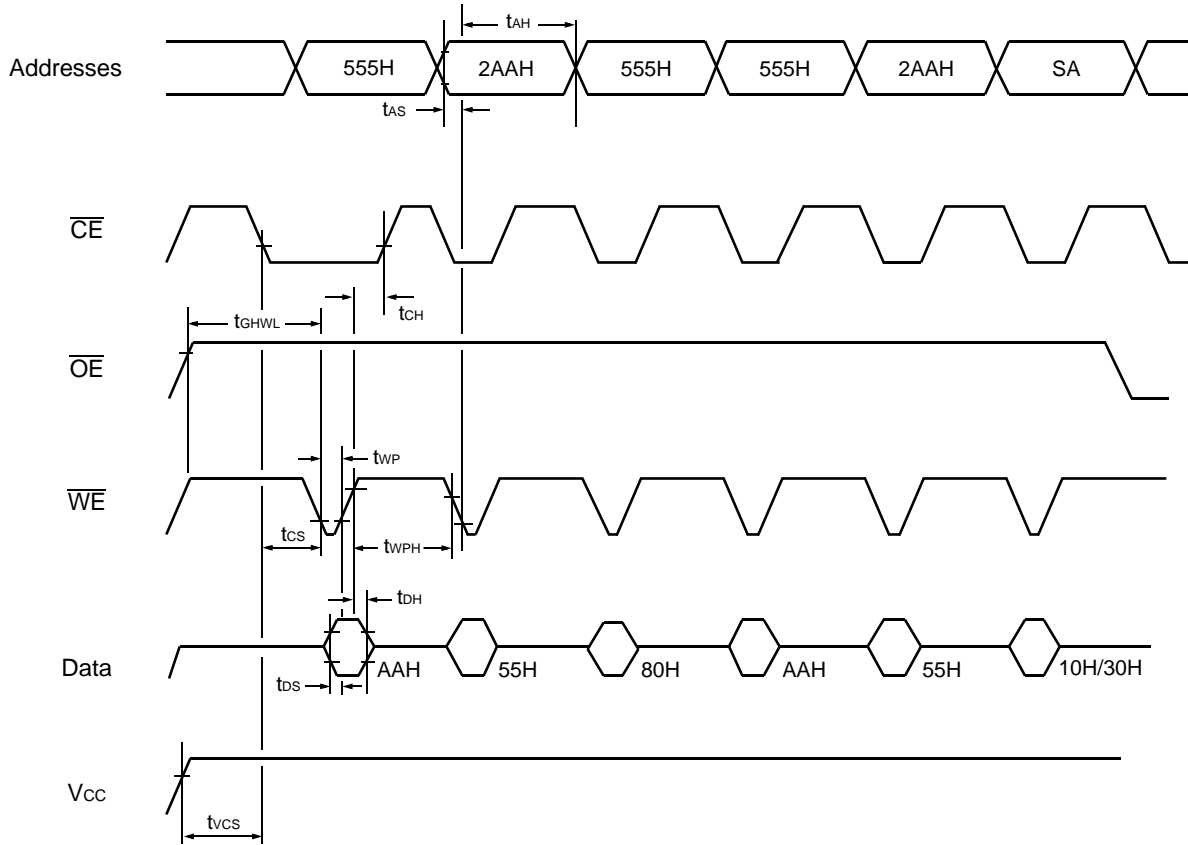
Notes: 1. SA is the sector address for Sector Erase. Addresses = 555H (Word), AAAH (Byte) for Chip Erase.
2. These waveforms are for the × 16 mode. (The addresses differ from × 8 mode.)

Figure 8   AC Waveforms Chip/Sector Erase Operations
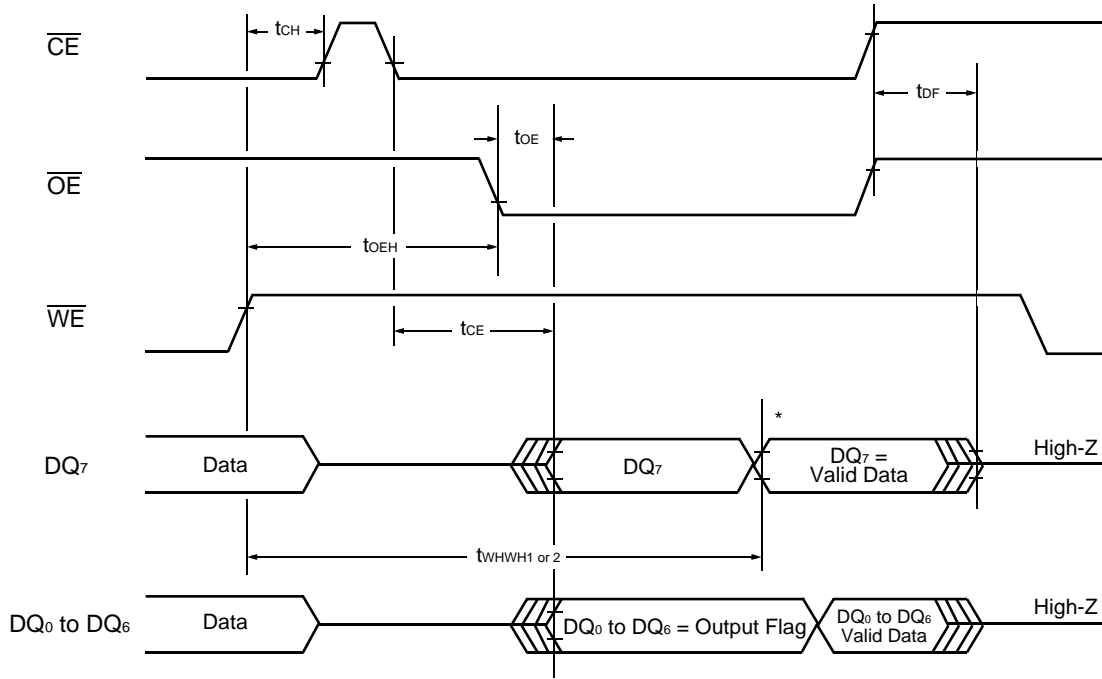
*: DQ$_7$ = Valid Data (The device has completed the Embedded operation).

Figure 9   AC Waveforms for $\overline{\text{Data}}$ Polling during Embedded Algorithm Operations
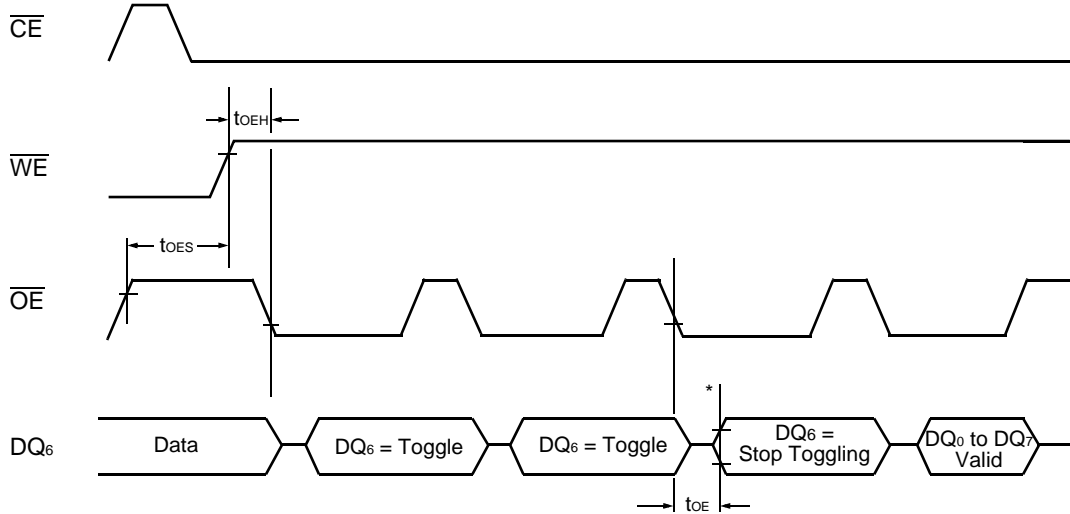
*: DQ$_6$ stops toggling (The device has completed the Embedded operation).

Figure 10   AC Waveforms for Toggle Bit I during Embedded Algorithm Operations

$\overline{CE}$

$\overline{WE}$

The rising edge of the last $\overline{WE}$ signal

Entire programming
or erase operations

RY/$\overline{BY}$

t_{BUSY}
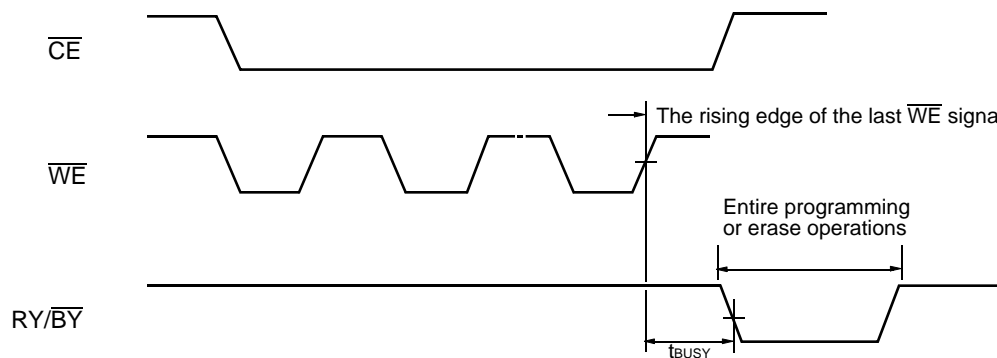
Figure 11   RY/$\overline{BY}$ Timing Diagram during Program/Erase Operations

$\overline{WE}$

$\overline{RESET}$

t_{RP}

t_{RB}

RY/$\overline{BY}$

t_{READY}
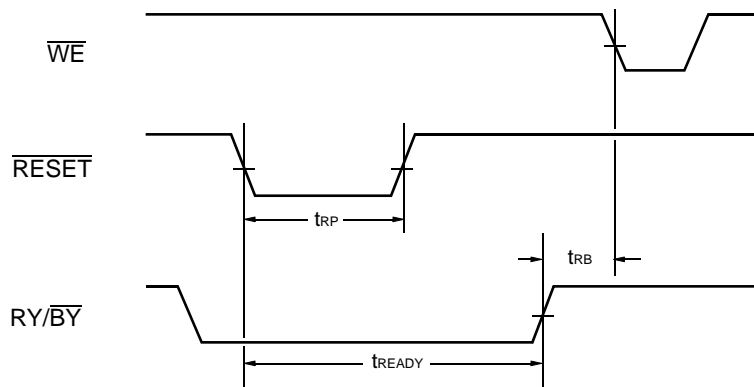
Figure 12 $\overline{RESET}$/RY/$\overline{BY}$ Timing Diagram
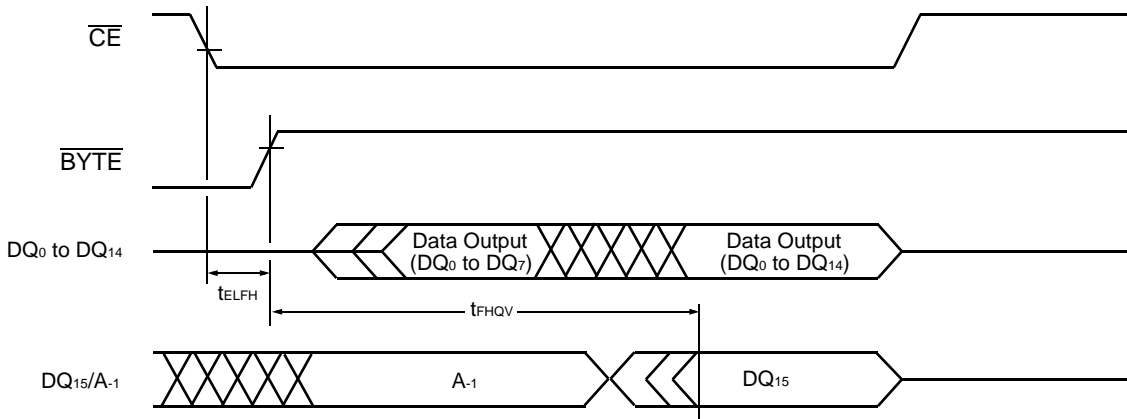
Figure 1   Timing Diagram for Word Mode Configuration
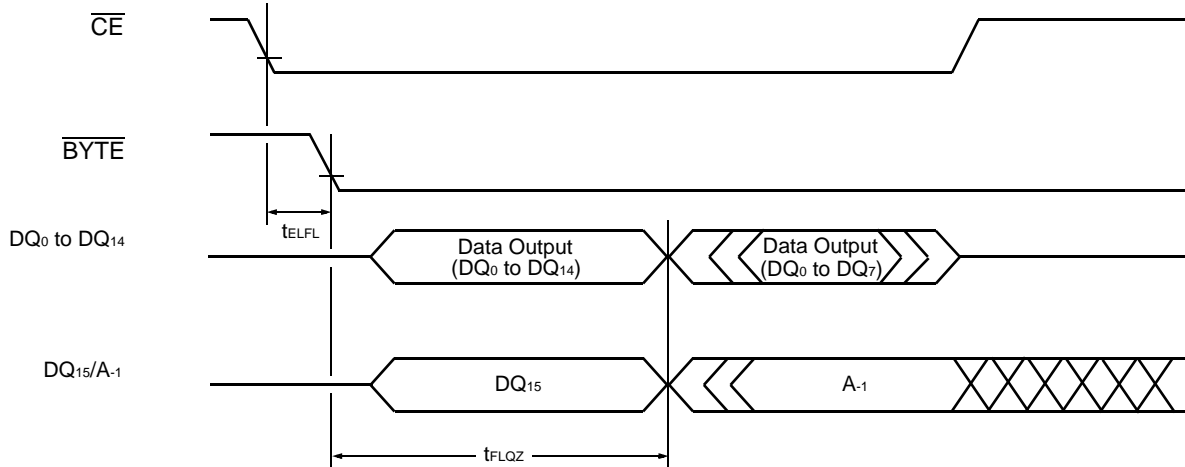
Figure 2   Timing Diagram for Byte Mode Configuration
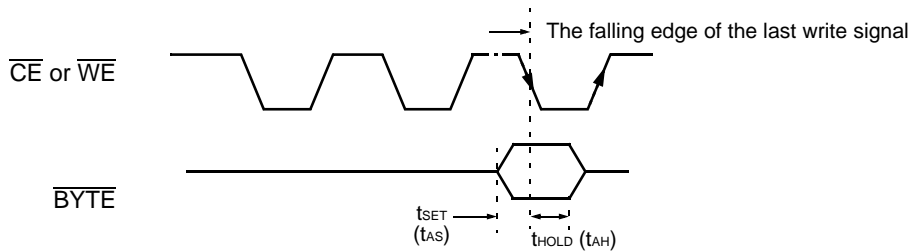
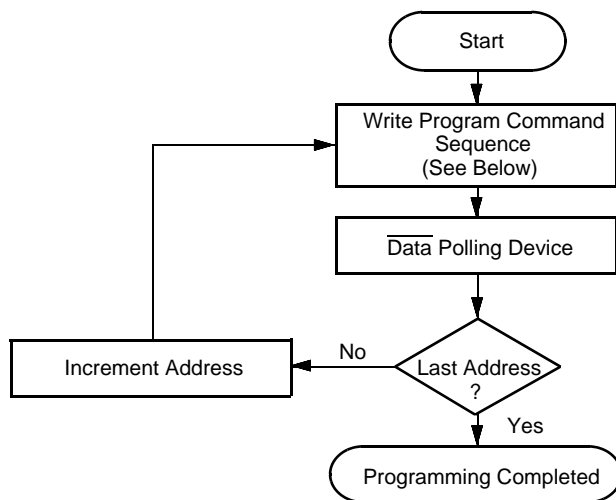**Figure 3 $\overline{\text{BYTE}}$ Timing Diagram for Write Operations**
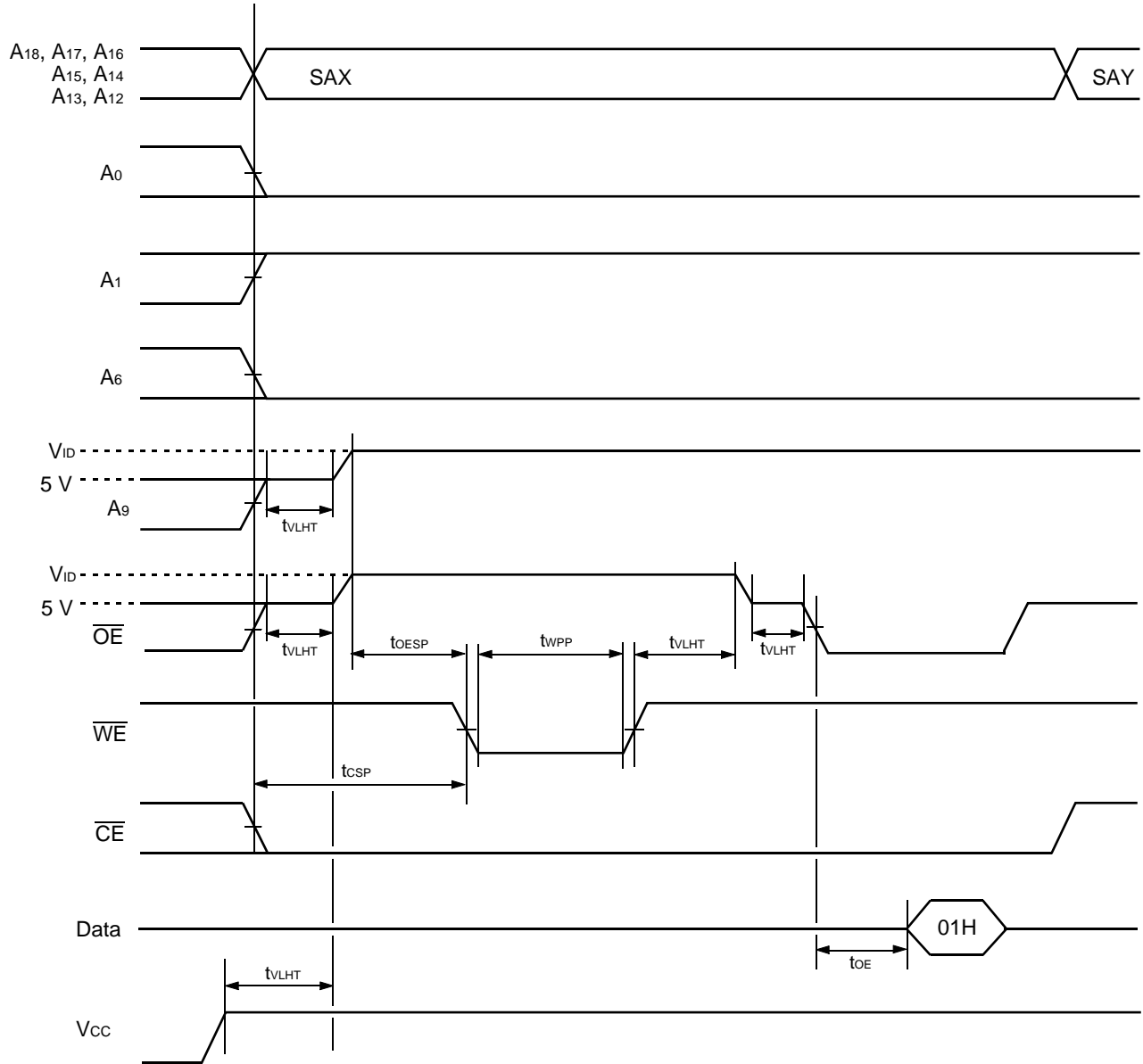
SAX = Sector Address for initial sector
SAY = Sector Address for next sector
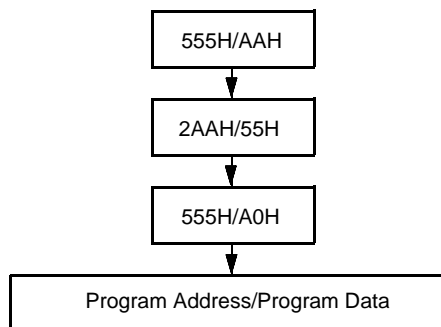**Note:** A-1 is VIL on byte mode.

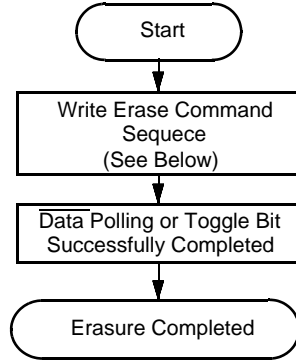**Figure 4   AC Waveforms for Sector Protection Timing Diagram**
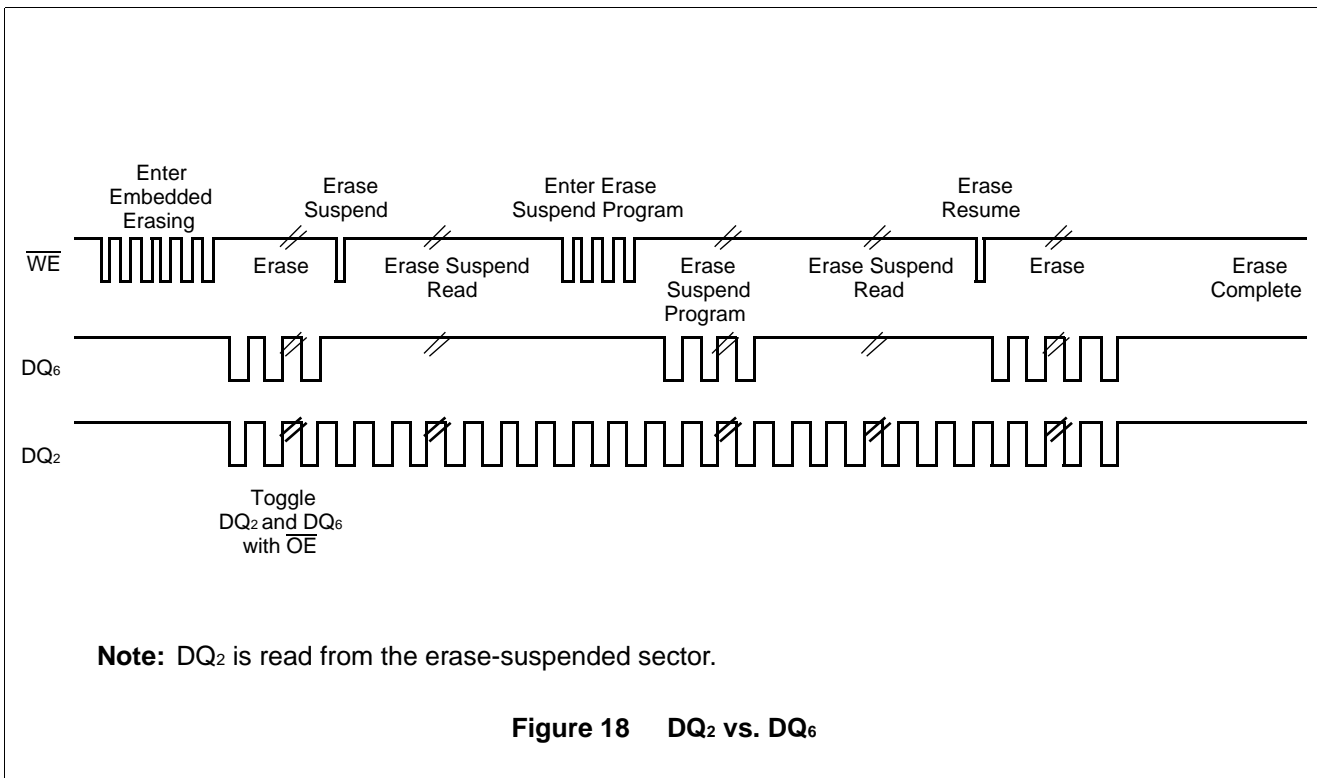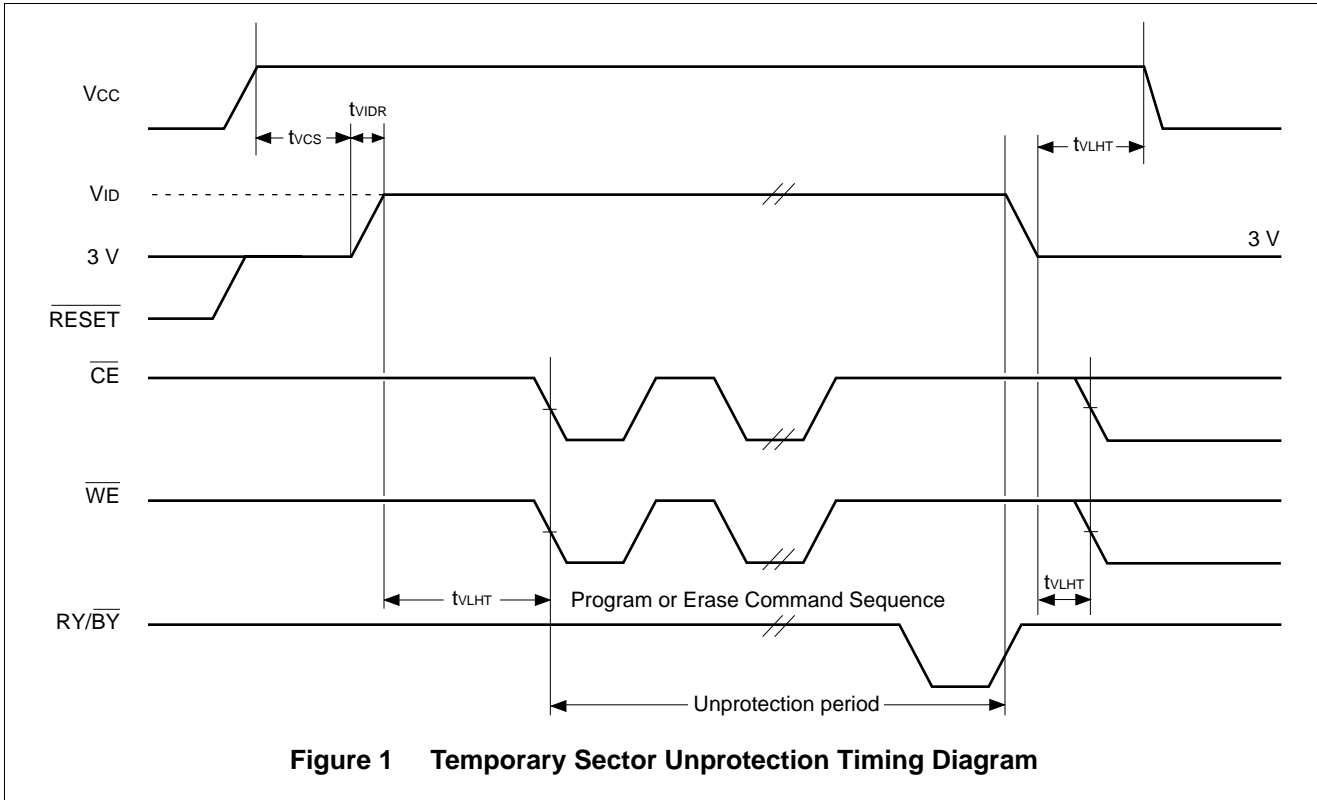
Figure 1   Temporary Sector Unprotection Timing Diagram

Note: DQ$_2$ is read from the erase-suspended sector.

Figure 18   DQ$_2$ vs. DQ$_6$

EMBEDDED ALGORITHMS

```
                    ┌─────────┐
                    │  Start  │
                    └────┬────┘
                         ▼
           ┌──────────────────────────┐
   ┌──────▶│  Write Program Command   │
   │       │        Sequence          │
   │       │       (See Below)        │
   │       └────────────┬─────────────┘
   │                    ▼
   │          ┌──────────────────┐
   │          │ Data Polling Device │
   │          └────────┬─────────┘
   │                   ▼
┌──────────────┐  No  ╱──────────╲
│  Increment   │◀─────  Last Address
│  Address     │      ╲    ?     ╱
└──────────────┘       ╲────────╱
                          │ Yes
                          ▼
              ┌───────────────────────┐
              │ Programming Completed  │
              └───────────────────────┘
```

Program Command Sequence* (Address/Command):

```
        ┌─────────────┐
        │  555H/AAH   │
        └──────┬──────┘
               ▼
        ┌─────────────┐
        │  2AAH/55H   │
        └──────┬──────┘
               ▼
        ┌─────────────┐
        │  555H/A0H   │
        └──────┬──────┘
               ▼
   ┌───────────────────────────┐
   │ Program Address/Program Data │
   └───────────────────────────┘
```

* : The sequence is applied for × 16 mode.
The addresses differ from × 8 mode.

Figure 2   Embedded Program™ Algorithm

EMBEDDED ALGORITHMS

```
              ┌─────────┐
              │  Start  │
              └─────────┘
                   │
         ┌─────────────────────┐
         │ Write Erase Command │
         │      Sequece        │
         │    (See Below)      │
         └─────────────────────┘
                   │
         ┌─────────────────────┐
         │ Data Polling or     │
         │ Toggle Bit          │
         │ Successfully        │
         │ Completed           │
         └─────────────────────┘
                   │
         ┌─────────────────────┐
         │ Erasure Completed   │
         └─────────────────────┘
```

Chip Erase Command Sequence*
(Address/Command):

- 555H/AAH
- 2AAH/55H
- 555H/80H
- 555H/AAH
- 2AAH/55H
- 555H/10H
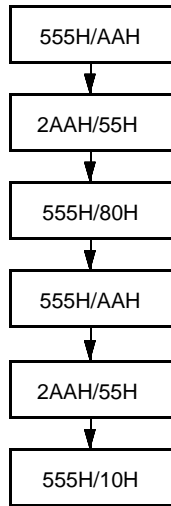
Individual Sector/Multiple Sector*
Erase Command Sequence
(Address/Command):

- 555H/AAH
- 2AAH/55H
- 555H/80H
- 555H/AAH
- 2AAH/55H
- Sector Address/30H
- Sector Address/30H
- Sector Address/30H
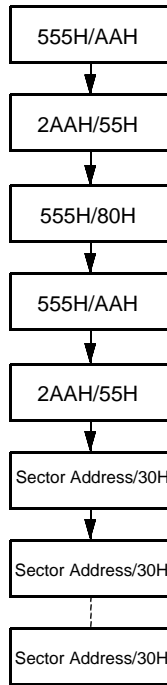
Additional sector erase commands are optional.

* : The sequence is applied for ×16 mode.
The addresses differ from ×8 mode.

Figure 3   Embedded Erase™ Algorithm
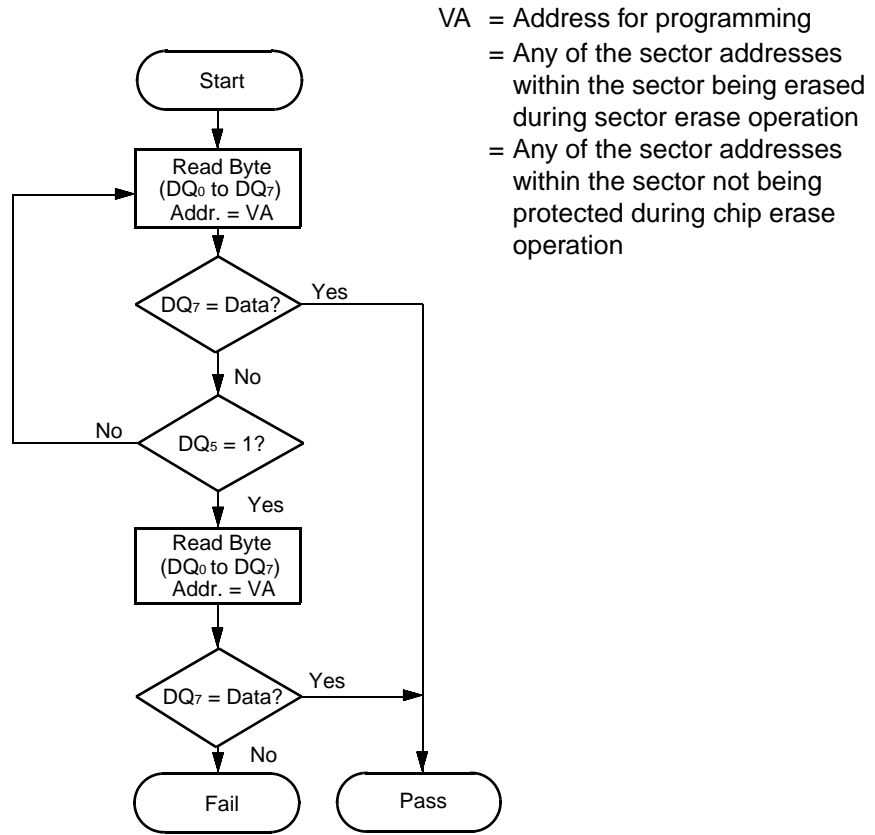
Note: DQ_7 is rechecked even if DQ_5 = "1" because DQ_7 may change simultaneously with DQ_5.

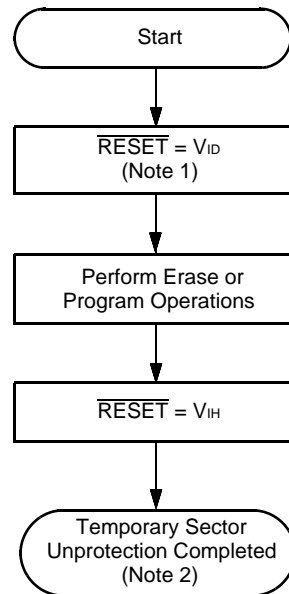**Figure 4 $\overline{Data}$ Polling Algorithm**

40
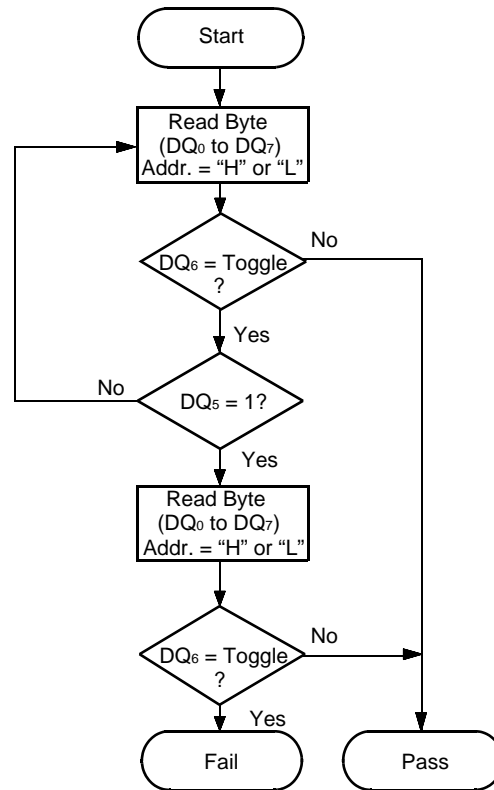
Note: DQ_6 is rechecked even if DQ_5 = "1" because DQ_6 may stop toggling at the same time as DQ_5 changing to "1".

Figure 5   Toggle Bit Algorithm

Start

Setup Sector Addr.
$(A_{18}, A_{17}, A_{16}, A_{15}, A_{14}, A_{13}, A_{12})$

PLSCNT = 1

$\overline{OE} = V_{ID}$, $A_9 = V_{ID}$,
$A_6 = \overline{CE} = V_{IL}$, $\overline{RESET} = V_{IH}$

Activate $\overline{WE}$ Pulse

Time out 100 µs

$\overline{WE} = V_{IH}$, $\overline{CE} = \overline{OE} = V_{IL}$
(A_9 should remain V_{ID})

Read from Sector
(Addr. = SA, $A_1 = 1$, $A_0 = V_6 = 0$)*

Increment PLSCNT

PLSCNT = 25?   No

Data = 01H?   No

Yes

Yes

Protect Another Sector?   Yes

No

Remove V_{ID} from A_9
Write Reset Command

Device Failed

Remove V_{ID} from A_9
Write Reset Command

Sector Protection
Completed

* : A_{-1} is V_{IL} on byte mode.

Figure 6   Sector Protection Algorithm

Figure 7   Temporary Sector Unprotection Algorithm

Notes: 1. All protected sectors unprotected.
            2. All previously protected sectors are protected once again.

■ ERASE AND PROGRAMMING PERFORMANCE

Parameter	Limits			Unit	Comments
	Min.	Typ.	Max.		
Sector Erase Time	—	1	8	sec	Excludes 00H programming prior to erasure
Word Programming Time	—	16	200	µs	Excludes system-level overhead
Byte Programming Time	—	8	150	µs	
Chip Programming Time	—	8.4	20	sec	Excludes system-level overhead
Erase/Program Cycle	100,000	—	—	cycles	

■ TSOP PIN CAPACITANCE

Parameter Symbol	Parameter Description	Test Setup	Typ.	Max.	Unit
C_{IN}	Input Capacitance	$V_{IN} = 0$	8	10	pF
C_{OUT}	Output Capacitance	$V_{OUT} = 0$	8	10	pF
C_{IN2}	Control Pin Capacitance	$V_{IN} = 0$	8.5	12.5	pF

Note: Test conditions $T_A = 25°C$, f = 1.0 MHz

■ SOP PIN CAPACITANCE

Parameter Symbol	Parameter Description	Test Setup	Typ.	Max.	Unit
C_{IN}	Input Capacitance	$V_{IN} = 0$	8	10.5	pF
C_{OUT}	Output Capacitance	$V_{OUT} = 0$	8	10	pF
C_{IN2}	Control Pin Capacitance	$V_{IN} = 0$	8.5	12.5	pF

Note: Test conditions $T_A = 25°C$, f = 1.0 MHz

■ PACKAGE DIMENSIONS

48-pin plastic TSOP(I)
(FPT-48P-M19)

*: Resin protrusion. (Each side: 0.15(.006) Max)

Details of "A" part

LEAD No.

INDEX

"A"

0.15(.006) MAX
0.35(.014) MAX
0.15(.006)   0.25(.010)

20.00±0.20
(.787±.008)
* 18.40±0.20
(.724±.008)

* 12.00±0.20
(.472±.008)
11.50REF
(.460)

1.10 +0.10 −0.05
(.043 +.004 −.002)
(Mounting height)

0.10(.004)

0.50(.0197)
TYP

0.05(0.02)MIN
(STAND OFF)

0.15±0.05
(.006±.002)

0.20±0.10
(.008±.004)

0.10(.004) Ⓜ

19.00±0.20
(.748±.008)

0.50±0.10
(.020±.004)
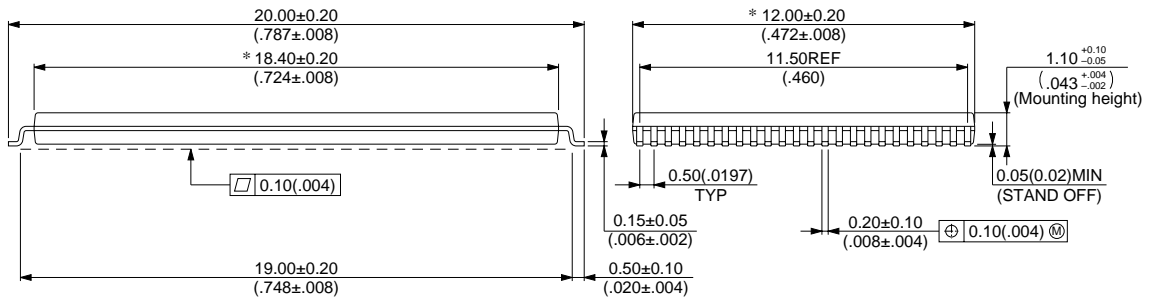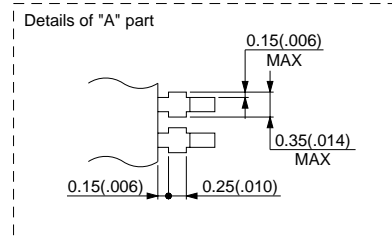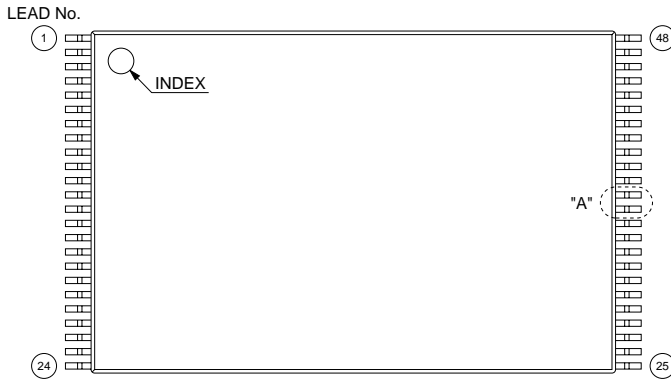
© 1996 FUJITSU LIMITED F48029S-2C-2

Dimensions in mm (inches)

(Continued)

48-pin plastic TSOP(I)
(FPT-48P-M20)

*: Resin protrusion. (Each side: 0.15(.006) Max)

LEAD No.

INDEX

"A"

Details of "A" part

0.15(.006) MAX

0.35(.014) MAX

0.15(.006)   0.25(.010)

19.00±0.20
(.748±.008)

0.50±0.10
(.020±.004)

0.15±0.10
(.006±.002)

0.20±0.10
(.008±.004)

0.10(.004) M

0.50(.0197)
TYP

0.05(0.02)MIN
STAND OFF

0.10(.004)

*18.40±0.20
(.724±.008)

20.00±0.20
(.787±.008)

11.50(.460)REF

*12.00±0.20(.472±.008)

$1.10^{+0.10}_{-0.05}$
$\left(.043^{+.004}_{-.002}\right)$
(Mounting height)
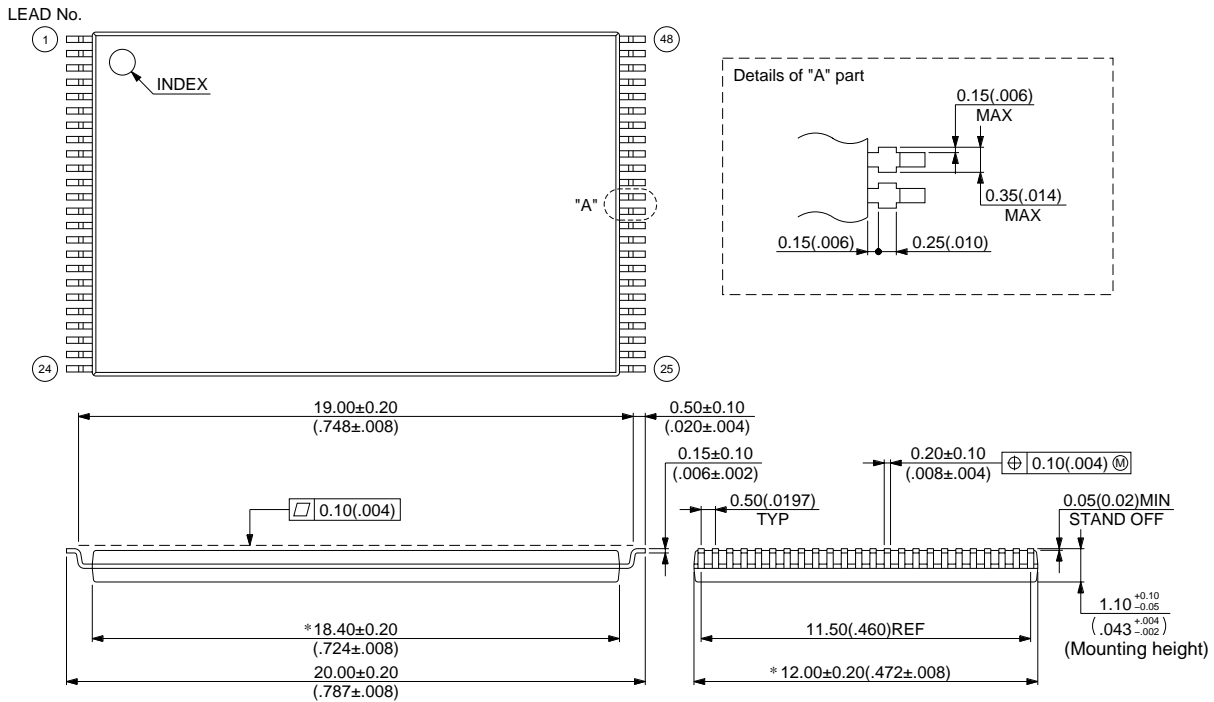
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Dimensions in mm (inches)

(Continued)

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(Continued)

44-pin plastic SOP
(FPT-44P-M16)

28.45 $^{+0.25}_{-0.20}$ (1.120 $^{+.010}_{-.008}$)

44   23

13.00±0.10   16.00±0.20
(.512±.004)   (.630±.008)

INDEX

LEAD No. 1   22

1.27(.050)TYP

2.35±0.15(.093±.006)
(Mounting height)

0.80±0.20
(.031±.008)

14.40±0.20
(.567±.008)

0.15±0.05
(.006±.002)

0.10(.004)

0.40 $^{+0.10}_{-0.05}$
(.016 $^{+.004}_{-.002}$)   Ø0.13(.005) Ⓜ

0.20 $^{+0.10}_{-0.15}$ (.008 $^{+.004}_{-.006}$)
(Stand off)

26.67(1.050)REF
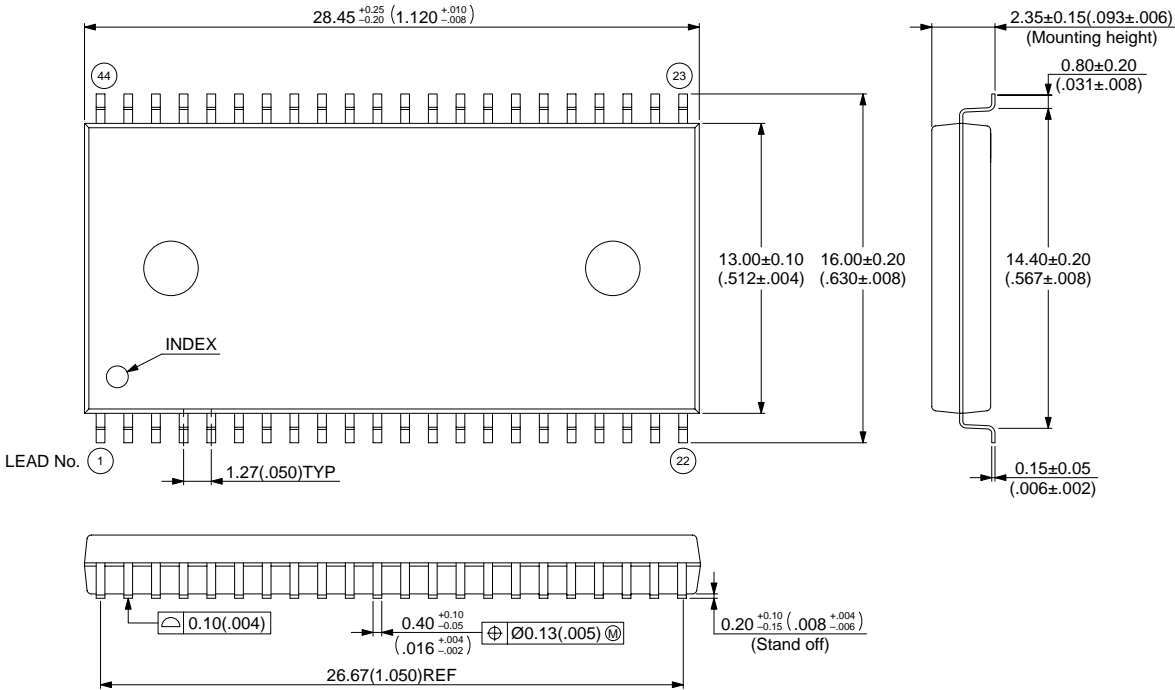
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